

TPS2291xx Ultra-small, Low On Resistance Load Switch With Controlled Turn-on

1 Features

- Integrated Single Load Switch
- Four Pin Wafer-Chip-Scale Package (Nom)
 - 0.9 mm x 0.9 mm, 0.5-mm Pitch, 0.5-mm Height (YZV)
- Input Voltage Range: 1.4 V to 5.5 V
- Low ON-Resistance
 - $r_{ON} = 60\text{ m}\Omega$ at $V_{IN} = 5\text{ V}$
 - $r_{ON} = 61\text{ m}\Omega$ at $V_{IN} = 3.3\text{ V}$
 - $r_{ON} = 74\text{ m}\Omega$ at $V_{IN} = 1.8\text{ V}$
 - $r_{ON} = 84\text{ m}\Omega$ at $V_{IN} = 1.5\text{ V}$
- 2-A Maximum Continuous Switch Current
- Low Threshold Control Input
- Controlled Slew-rate
- Under-Voltage Lock Out
- Full-Time Reverse Current Protection
- Quick Output Discharge Transistor (TPS22913B/C Devices)

2 Applications

- Notebook Computer and Ultrabook™
- Tablets and Set-Top-Boxes
- Portable Industrial / Medical Equipment
- Portable Media Players
- Point Of Sale Pins
- GPS Navigation Devices
- Digital Cameras
- Portable Instrumentation
- Smartphones / Wireless Handsets

3 Description

The TPS22910A, TPS22912C, and TPS22913B/C are small, low r_{ON} load switches with controlled turn on. The device contains a P-channel MOSFET that can operate over an input voltage range of 1.4 V to 5.5 V. The switch is controlled by an on/off input (ON), which is capable of interfacing directly with low-voltage GPIO control signals.

The TPS22910A, TPS22912C, and TPS22913B/C devices provide reverse current protection in ON and OFF states. An internal reverse voltage comparator disables the power-switch when the output voltage (V_{OUT}) is driven higher than the input voltage (V_{IN}), by V_{RCP} , to quickly (10 μs typ) stop the flow of current towards the input side of the switch. Reverse current protection is always active, even when the power-switch is disabled. Additionally, under-voltage lockout (UVLO) protection turns the switch off if the input voltage is too low.

The TPS22913B/C contains a 150- Ω on-chip load resistor for quick output discharge when the switch is turned off.

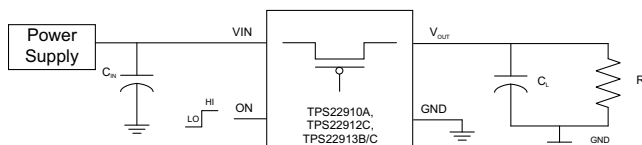
This family of devices have various slew rate options to avoid inrush current (see [Device Comparison Table](#) for details), are available in an ultra-small, space-saving 4-pin WCSP packages, and are characterized for operation over the free-air temperature range of -40°C to 85°C .

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TPS22910A	DSBGA (4)	0.90 mm x 0.90 mm
TPS22912C		
TPS22913B		
TPS22913C		

(1) For all available packages, see the orderable addendum at the end of the datasheet.

4 Simplified Schematic



On-State Resistance vs Input Voltage

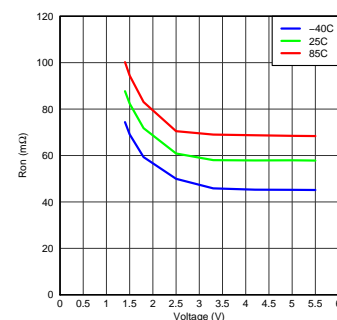


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5 Revision History

Changes from Revision C (May 2013) to Revision D

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•	Combined TPS22910A, TPS22912C, and TPS22913B/C datasheets.	1
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6 Device Comparison Table

DEVICE	r_{ON} (typ) at 3.3 V	RISE TIME at 3.3V (typ)	QUICK OUTPUT DISCHARGE	MAXIMUM OUTPUT CURRENT	ENABLE
TPS22910A	61 m Ω	1 μ s	No	2 A	Active Low
TPS22912C	61 m Ω	1000 μ s	No	2 A	Active High
TPS22913B	61 m Ω	66 μ s	Yes	2 A	Active High
TPS22913C	61 m Ω	660 μ s	Yes	2 A	Active High

7 Pin Configuration and Functions

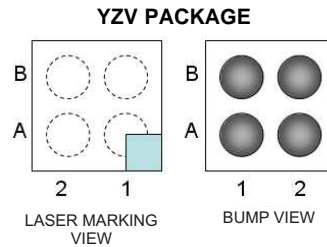


Table 1. Pin Assignments

B	ON	GND
A	VIN	VOUT
	2	1

Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
VOUT	A1	O	Switch output
VIN	A2	I	Switch input, use a bypass capacitor (ceramic) to ground.
GND	B1	–	Ground
ON	B2	I	Switch control input, active low. Do not leave floating

8 Specifications

8.1 Absolute Maximum Ratings

		MIN	MAX	UNIT
V_{IN}	Input voltage range	-0.3	6	V
V_{OUT}	Output voltage range	-0.3	6	V
V_{ON}	Input voltage range	-0.3	6	V
I_{MAX}	Maximum continuous switch current	2	2	A
I_{PLS}	Maximum pulsed switch current, pulse < 300 μ s, 2% duty cycle	2.5	2.5	A
T_A	Operating free-air temperature range	-40	85	$^{\circ}$ C
T_J	Maximum junction temperature	125	125	$^{\circ}$ C

8.2 Handling Ratings

		MIN	MAX	UNIT	
T_{stg}	Storage temperature range	-65	150	$^{\circ}$ C	
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	-2	2	kV
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	-1	1	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Pins listed as 2 kV may actually have higher performance.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Pins listed as 1kV may actually have higher performance.

8.3 Recommended Operating Conditions

			MIN	MAX	UNIT
V_{IN}	Input voltage range		1.4	5.5	V
V_{ON}	ON voltage range		0	5.5	V
V_{OUT}	Output voltage range			V_{IN}	
V_{IH}	High-level input voltage, ON	$V_{IN} = 1.4$ V to 5.5 V	1.1	5.5	V
V_{IL}	Low-level input voltage, ON	$V_{IN} = 3.61$ V to 5.5 V		0.6	V
		$V_{IN} = 1.4$ V to 3.6 V		0.4	V
C_{IN}	Input capacitor		1 ⁽¹⁾		μ F

(1) Refer to the application section.

8.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TPS22910	TPS22912	TPS22913	UNIT
		CSP	CSP	CSP	
		4 PINS	4 PINS	4 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	189.1	189.1	189.1	$^{\circ}$ C/W
$R_{\theta Jctop}$	Junction-to-case (top) thermal resistance	1.9	1.9	1.9	
$R_{\theta JB}$	Junction-to-board thermal resistance	36.8	36.8	36.8	
Ψ_{JT}	Junction-to-top characterization parameter	11.3	11.3	11.3	
Ψ_{JB}	Junction-to-board characterization parameter	36.8	36.8	36.8	
$R_{\theta Jcbot}$	Junction-to-case (bottom) thermal resistance	–	–	–	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

8.5 Electrical Characteristics

For TPS22910A $V_{ON} = 0$ V where enabled and $V_{ON} = V_{IN}$ where disabled. For TPS22912C and TPS22913B/C $V_{ON} = V_{IN}$ where enabled and $V_{ON} = 0$ V where disabled. $V_{IN} = 1.4$ V to 5.5 V, $T_A = -40^\circ\text{C}$ to 85°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T_A	MIN	TYP	MAX	UNIT
I_{IN} Quiescent current	$I_{OUT} = 0$ mA, $V_{IN} = 5.25$ V, $V_{ON} = \text{Enabled}$	Full		2	10	μA
	$I_{OUT} = 0$ mA, $V_{IN} = 4.2$ V, $V_{ON} = \text{Enabled}$			2	7.0	
	$I_{OUT} = 0$ mA, $V_{IN} = 3.6$ V, $V_{ON} = \text{Enabled}$			2	7.0	
	$I_{OUT} = 0$ mA, $V_{IN} = 2.5$ V, $V_{ON} = \text{Enabled}$			0.9	5	
	$I_{OUT} = 0$ mA, $V_{IN} = 1.5$ V, $V_{ON} = \text{Enabled}$			0.7	5	
$I_{IN(\text{off})}$ Off supply current	$R_L = 1$ M Ω , $V_{IN} = 5.25$ V, $V_{ON} = \text{Disabled}$	Full		1.2	10	μA
	$R_L = 1$ M Ω , $V_{IN} = 4.2$ V, $V_{ON} = \text{Disabled}$			0.2	7.0	
	$R_L = 1$ M Ω , $V_{IN} = 3.6$ V, $V_{ON} = \text{Disabled}$			0.1	7.0	
	$R_L = 1$ M Ω , $V_{IN} = 2.5$ V, $V_{ON} = \text{Disabled}$			0.1	5	
	$R_L = 1$ M Ω , $V_{IN} = 1.5$ V, $V_{ON} = \text{Disabled}$			0.1	5	
$I_{IN(\text{Leakage})}$ Leakage current	$V_{OUT} = 0$ V, $V_{IN} = 5.25$ V, $V_{ON} = \text{Disabled}$	Full		1.2	10	μA
	$V_{OUT} = 0$ V, $V_{IN} = 4.2$ V, $V_{ON} = \text{Disabled}$			0.2	7.0	
	$V_{OUT} = 0$ V, $V_{IN} = 3.6$ V, $V_{ON} = \text{Disabled}$			0.1	7.0	
	$V_{OUT} = 0$ V, $V_{IN} = 2.5$ V, $V_{ON} = \text{Disabled}$			0.1	5	
	$V_{OUT} = 0$ V, $V_{IN} = 1.5$ V, $V_{ON} = \text{Disabled}$			0.1	5	
r_{ON} On-resistance	$V_{IN} = 5.25$ V, $I_{OUT} = -200$ mA	25 $^\circ\text{C}$		60	80	$\text{m}\Omega$
		Full			110	
	$V_{IN} = 5.0$ V, $I_{OUT} = -200$ mA	25 $^\circ\text{C}$		60	80	
		Full			110	
	$V_{IN} = 4.2$ V, $I_{OUT} = -200$ mA	25 $^\circ\text{C}$		60	80	
		Full			110	
	$V_{IN} = 3.3$ V, $I_{OUT} = -200$ mA	25 $^\circ\text{C}$		60.7	80	
		Full			110	
	$V_{IN} = 2.5$ V, $I_{OUT} = -200$ mA	25 $^\circ\text{C}$		63.4	90	
		Full			120	
	$V_{IN} = 1.8$ V, $I_{OUT} = -200$ mA	25 $^\circ\text{C}$		74.2	100	
		Full			130	
	$V_{IN} = 1.5$ V, $I_{OUT} = -200$ mA	25 $^\circ\text{C}$		83.9	120	
		Full			150	
RDP ⁽¹⁾ Output pull down resistance	$V_{IN} = 3.3$ V, $I_{OUT} = 30$ mA, $V_{ON} = 0$	25 $^\circ\text{C}$		153	200	Ω
UVLO Under voltage lockout	V_{IN} increasing, $V_{ON} = 0$ V, $I_{OUT} = -100$ mA V_{IN} decreasing, $V_{ON} = 0$ V, $R_L = 10$ Ω	Full			1.2	V
			0.50			
I_{ON} ON input leakage current	$V_{ON} = 1.4$ V to 5.25 V or GND	Full			1	μA
V_{RCP} Reverse current voltage threshold	TPS22910A, TPS22913B/C			44		mV
	TPS22912C			54		
t_{DELAY} Reverse current response delay	$V_{IN} = 5$ V			10		μs
$I_{RCP(\text{leak})}$ Reverse current protection leakage after reverse current event.	$V_{OUT} - V_{IN} > V_{RCP}$	25 $^\circ\text{C}$		0.3		μA

(1) Only applies to the TPS22913B/C devices

8.6 Switching Characteristics, TPS22910A

PARAMETER		TEST CONDITION	TYP	UNIT
VIN = 5 V, TA = 25°C (unless otherwise noted)				
t _{ON}	Turn-ON time	R _L = 10 Ω, C _L = 0.1 μF	2	μs
t _{OFF}	Turn-OFF time	R _L = 10 Ω, C _L = 0.1 μF	5.5	
t _R	VOUT rise time	R _L = 10 Ω, C _L = 0.1 μF	1	
t _F	VOUT fall time	R _L = 10 Ω, C _L = 0.1 μF	3	
VIN = 3.3 V, TA = 25°C (unless otherwise noted)				
t _{ON}	Turn-ON time	R _L = 10 Ω, C _L = 0.1 μF	2.5	μs
t _{OFF}	Turn-OFF time	R _L = 10 Ω, C _L = 0.1 μF	7	
t _R	VOUT rise time	R _L = 10 Ω, C _L = 0.1 μF	1	
t _F	VOUT fall time	R _L = 10 Ω, C _L = 0.1 μF	3.5	
VIN = 1.5 V, TA = 25°C (unless otherwise noted)				
t _{ON}	Turn-ON time	R _L = 10 Ω, C _L = 0.1 μF	4.5	μs
t _{OFF}	Turn-OFF time	R _L = 10 Ω, C _L = 0.1 μF	16.5	
t _R	VOUT rise time	R _L = 10 Ω, C _L = 0.1 μF	2	
t _F	VOUT fall time	R _L = 10 Ω, C _L = 0.1 μF	7	

8.7 Switching Characteristics, TPS22912C

PARAMETER		TEST CONDITION	TYP	UNIT
VIN = 5 V, TA = 25°C (unless otherwise noted)				
t _{ON}	Turn-ON time	R _L = 10 Ω, C _L = 0.1 μF	840	μs
t _{OFF}	Turn-OFF time	R _L = 10 Ω, C _L = 0.1 μF	6.6	
t _R	VOUT rise time	R _L = 10 Ω, C _L = 0.1 μF	912	
t _F	VOUT fall time	R _L = 10 Ω, C _L = 0.1 μF	3	
VIN = 3.3 V, TA = 25°C (unless otherwise noted)				
t _{ON}	Turn-ON time	R _L = 10 Ω, C _L = 0.1 μF	1147	μs
t _{OFF}	Turn-OFF time	R _L = 10 Ω, C _L = 0.1 μF	8.6	
t _R	VOUT rise time	R _L = 10 Ω, C _L = 0.1 μF	1030	
t _F	VOUT fall time	R _L = 10 Ω, C _L = 0.1 μF	3	
VIN = 1.5 V, TA = 25°C (unless otherwise noted)				
t _{ON}	Turn-ON time	R _L = 10 Ω, C _L = 0.1 μF	2513	μs
t _{OFF}	Turn-OFF time	R _L = 10 Ω, C _L = 0.1 μF	17.4	
t _R	VOUT rise time	R _L = 10 Ω, C _L = 0.1 μF	1970	
t _F	VOUT fall time	R _L = 10 Ω, C _L = 0.1 μF	6.5	

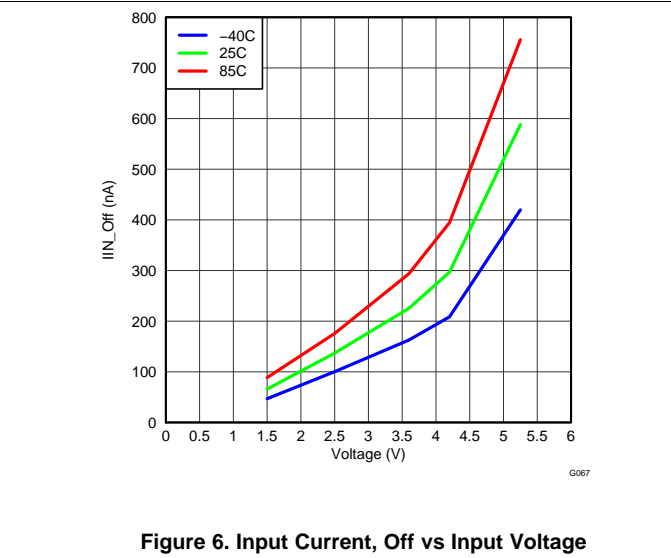
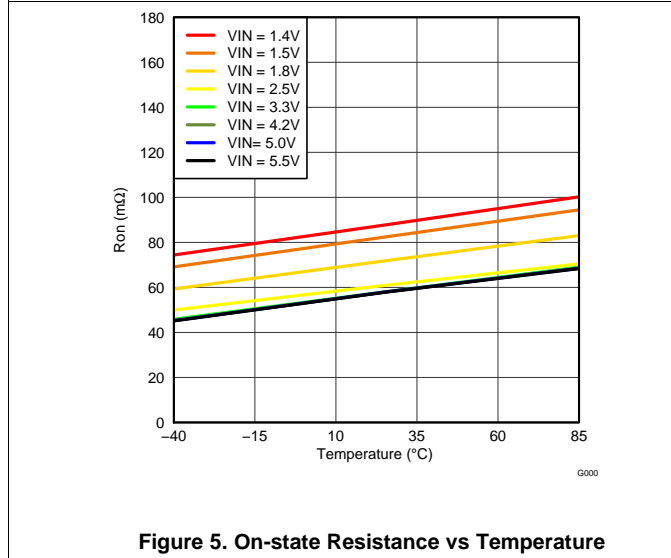
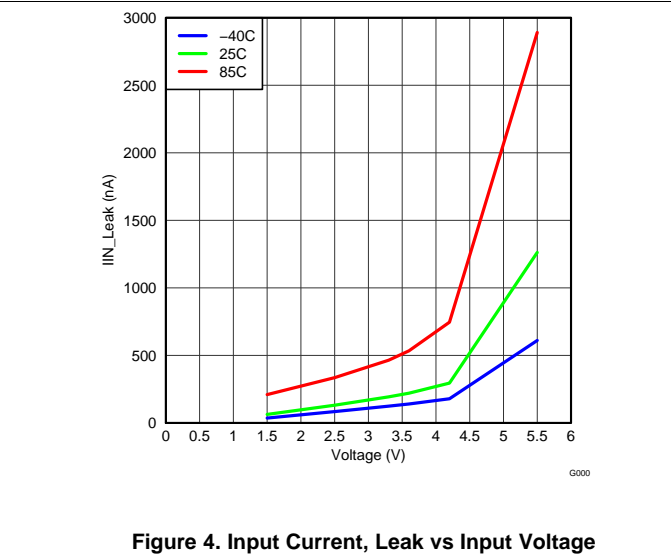
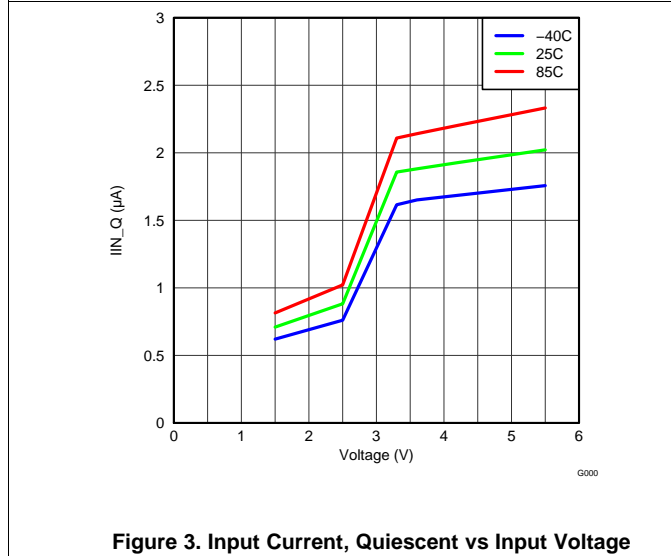
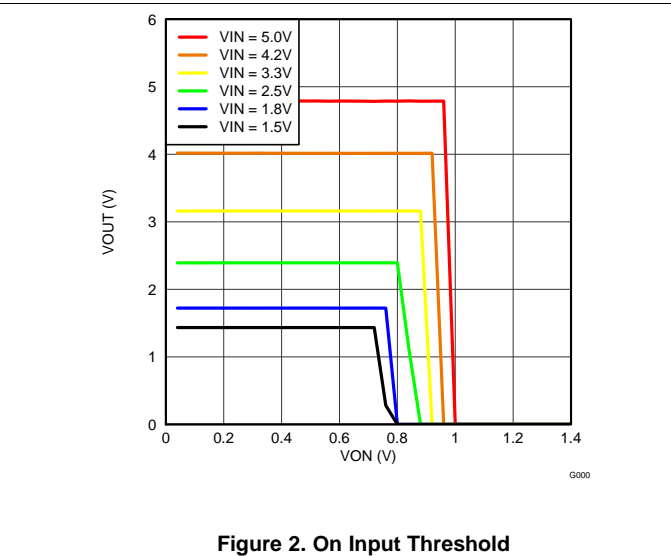
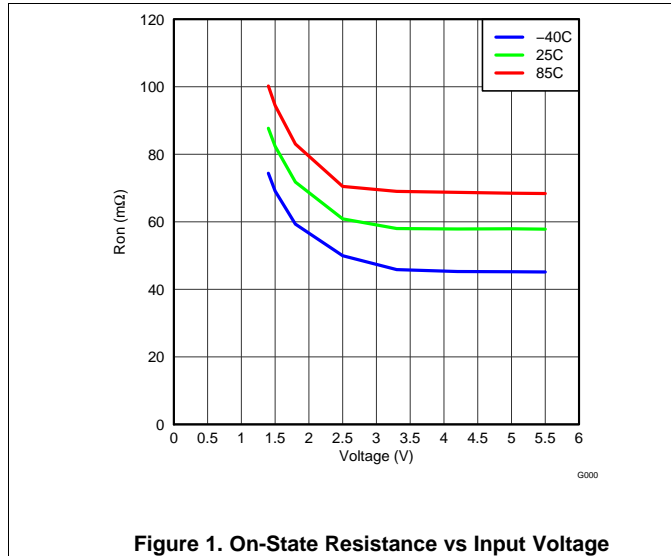
8.8 Switching Characteristics, TPS22913B

PARAMETER		TEST CONDITION	TYP	UNIT
VIN = 5 V, TA = 25°C (unless otherwise noted)				
t _{ON}	Turn-ON time	R _L = 10 Ω, C _L = 0.1 μF	76	μs
t _{OFF}	Turn-OFF time	R _L = 10 Ω, C _L = 0.1 μF	6.6	
t _R	VOUT rise time	R _L = 10 Ω, C _L = 0.1 μF	82	
t _F	VOUT fall time	R _L = 10 Ω, C _L = 0.1 μF	3	
VIN = 3.3 V, TA = 25°C (unless otherwise noted)				
t _{ON}	Turn-ON time	R _L = 10 Ω, C _L = 0.1 μF	102	μs
t _{OFF}	Turn-OFF time	R _L = 10 Ω, C _L = 0.1 μF	8.5	
t _R	VOUT rise time	R _L = 10 Ω, C _L = 0.1 μF	97	
t _F	VOUT fall time	R _L = 10 Ω, C _L = 0.1 μF	3	
VIN = 1.5 V, TA = 25°C (unless otherwise noted)				
t _{ON}	Turn-ON time	R _L = 10 Ω, C _L = 0.1 μF	234	μs
t _{OFF}	Turn-OFF time	R _L = 10 Ω, C _L = 0.1 μF	17	
t _R	VOUT rise time	R _L = 10 Ω, C _L = 0.1 μF	244	
t _F	VOUT fall time	R _L = 10 Ω, C _L = 0.1 μF	6.5	

8.9 Switching Characteristics, TPS22913C

PARAMETER		TEST CONDITION	TYP	UNIT
VIN = 5 V, TA = 25°C (unless otherwise noted)				
t _{ON}	Turn-ON time	R _L = 10 Ω, C _L = 0.1 μF	770	μs
t _{OFF}	Turn-OFF time	R _L = 10 Ω, C _L = 0.1 μF	6.6	
t _R	VOUT rise time	R _L = 10 Ω, C _L = 0.1 μF	838	
t _F	VOUT fall time	R _L = 10 Ω, C _L = 0.1 μF	3	
VIN = 3.3 V, TA = 25°C (unless otherwise noted)				
t _{ON}	Turn-ON time	R _L = 10 Ω, C _L = 0.1 μF	1048	μs
t _{OFF}	Turn-OFF time	R _L = 10 Ω, C _L = 0.1 μF	8.6	
t _R	VOUT rise time	R _L = 10 Ω, C _L = 0.1 μF	980	
t _F	VOUT fall time	R _L = 10 Ω, C _L = 0.1 μF	3	
VIN = 1.5 V, TA = 25°C (unless otherwise noted)				
t _{ON}	Turn-ON time	R _L = 10 Ω, C _L = 0.1 μF	2344	μs
t _{OFF}	Turn-OFF time	R _L = 10 Ω, C _L = 0.1 μF	18	
t _R	VOUT rise time	R _L = 10 Ω, C _L = 0.1 μF	1823	
t _F	VOUT fall time	R _L = 10 Ω, C _L = 0.1 μF	6.5	

8.10 Typical DC Characteristics



Typical DC Characteristics (continued)

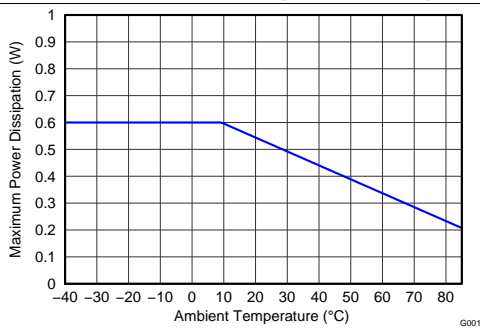


Figure 7. Allowable Power Dissipation

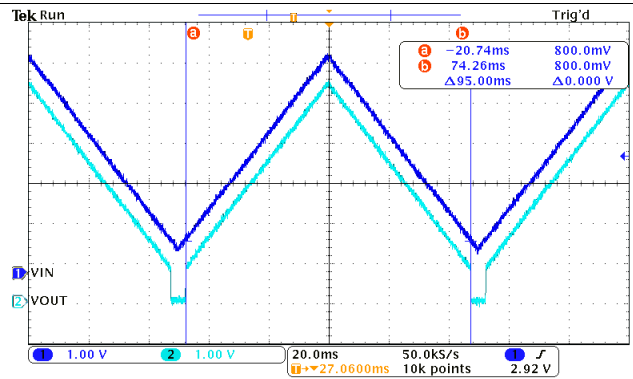


Figure 8. ULVO Response $I_{OUT} = -100 \text{ mA}$

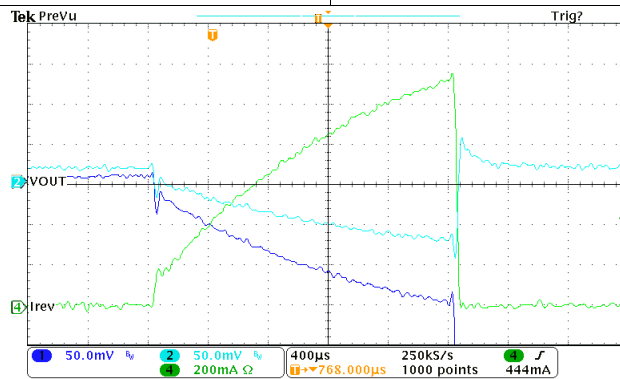


Figure 9. Reverse Current Protection $V_{OUT} = 5 \text{ V}$ (Measured with -5 V Offset), Ramping Load on V_{in}

8.11 Typical AC Characteristics, TPS22910A

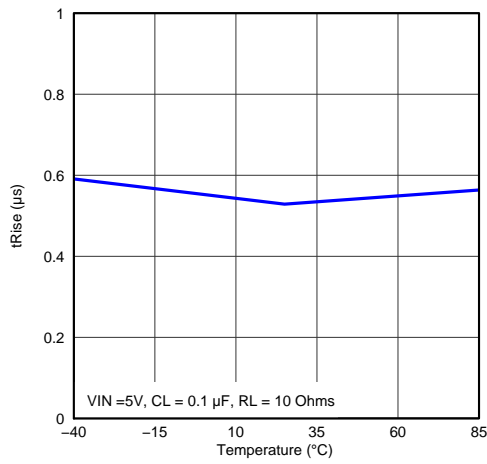


Figure 10. Rise Time vs Temperature

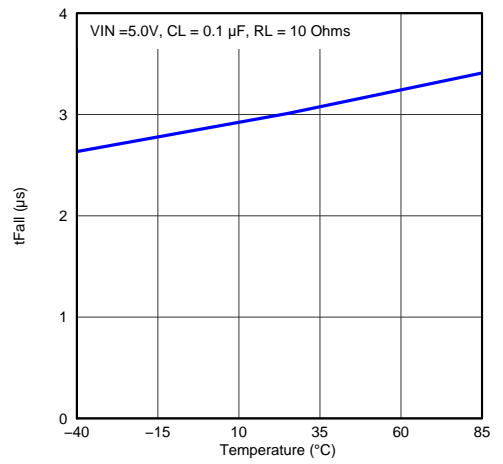


Figure 11. Fall Time vs Temperature

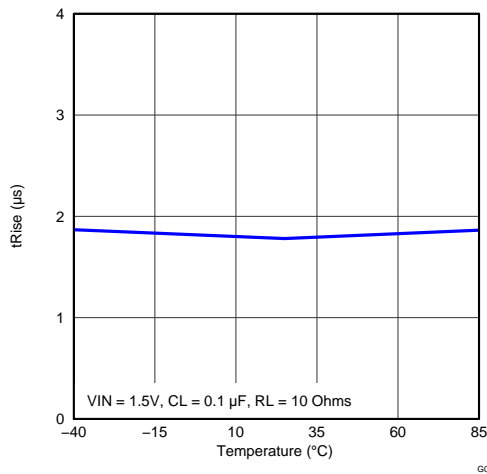


Figure 12. Rise Time vs Temperature

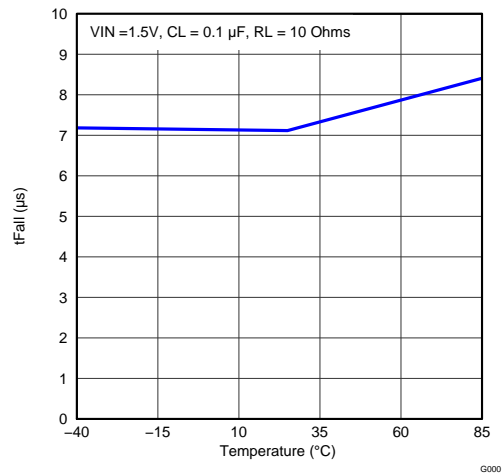


Figure 13. Fall Time vs Temperature

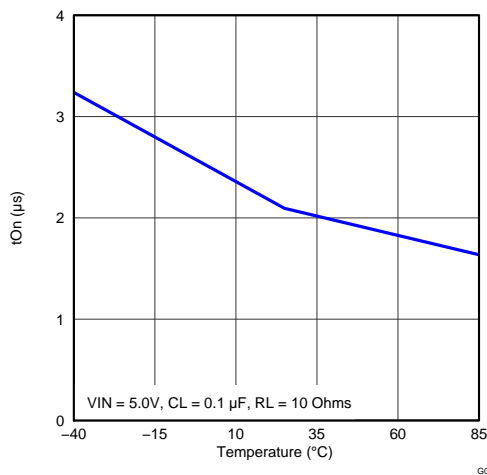


Figure 14. Turn-on Time vs Temperature

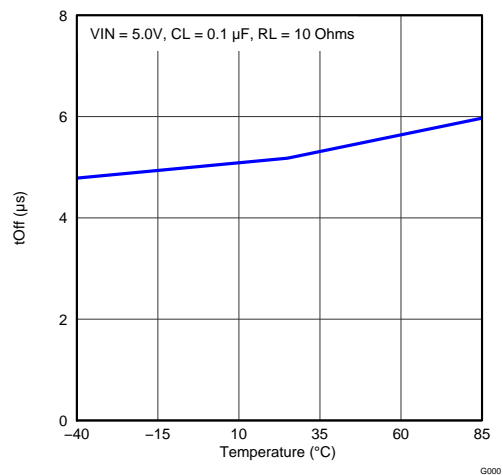


Figure 15. Turn-off Time vs Temperature

Typical AC Characteristics, TPS22910A (continued)

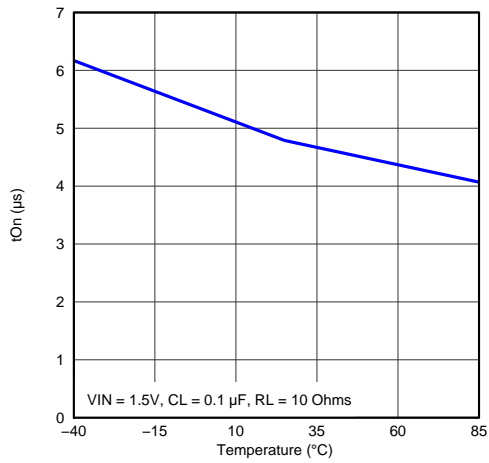


Figure 16. Turn-on Time vs Temperature

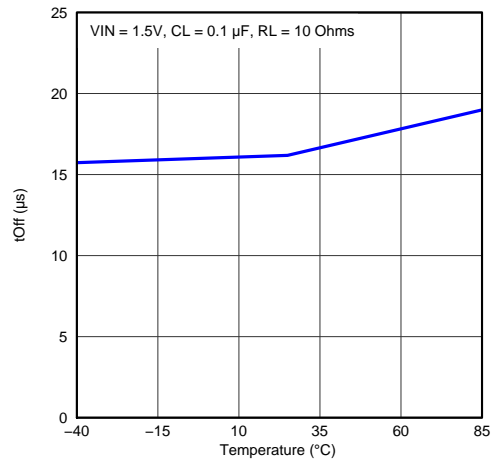


Figure 17. Turn-off Time vs Temperature

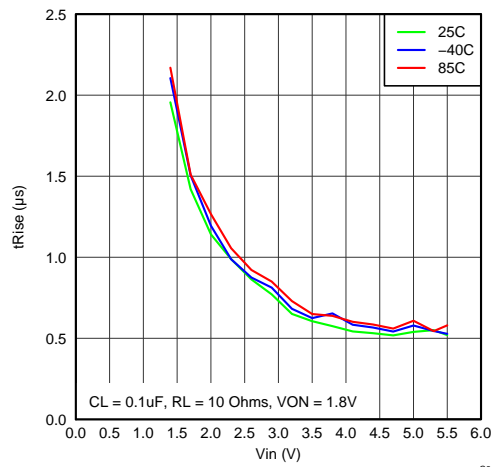


Figure 18. Rise Time vs Input Voltage

8.12 Typical AC Characteristics, TPS22912C

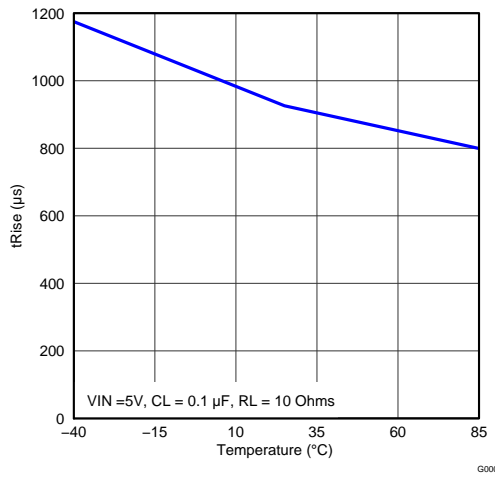


Figure 19. Rise Time vs Temperature

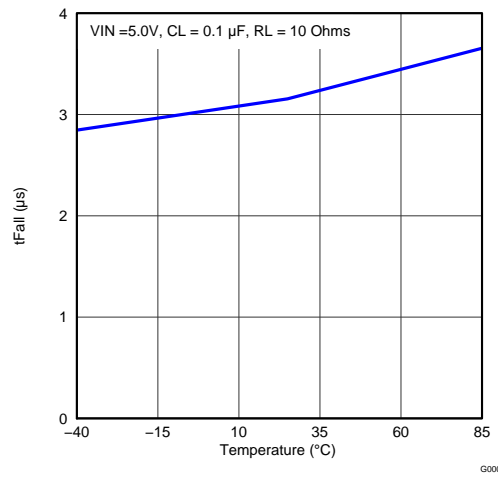


Figure 20. Fall Time vs Temperature

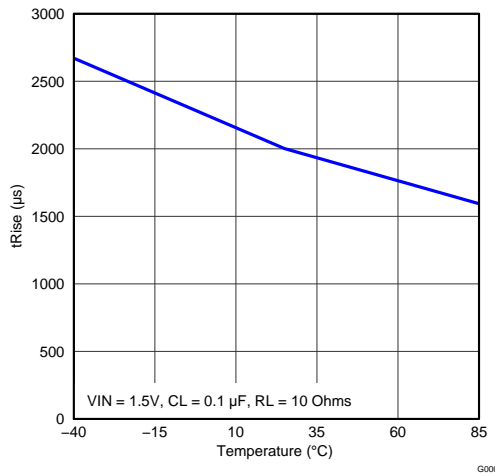


Figure 21. Rise Time vs Temperature

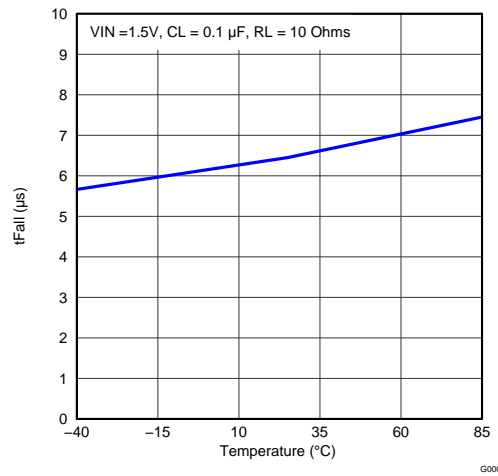


Figure 22. Fall Time vs Temperature

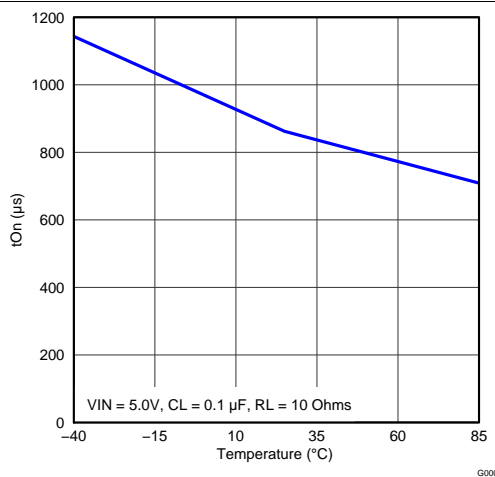


Figure 23. Turn-on Time vs Temperature

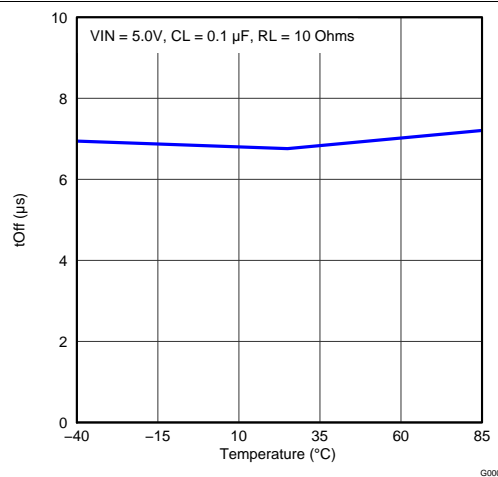


Figure 24. Turn-off Time vs Temperature

Typical AC Characteristics, TPS22912C (continued)

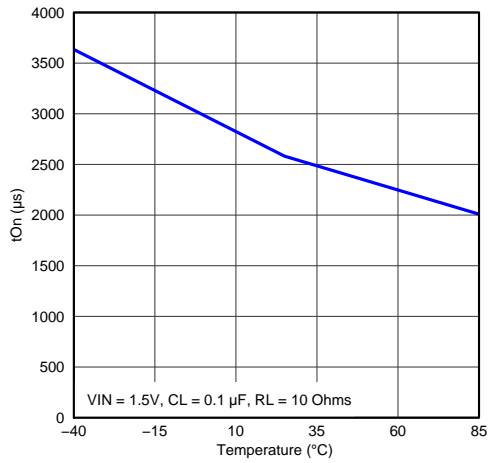


Figure 25. Turn-on Time vs Temperature

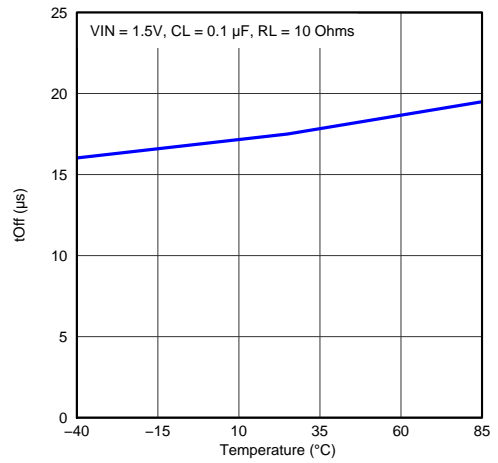


Figure 26. Turn-off Time vs Temperature

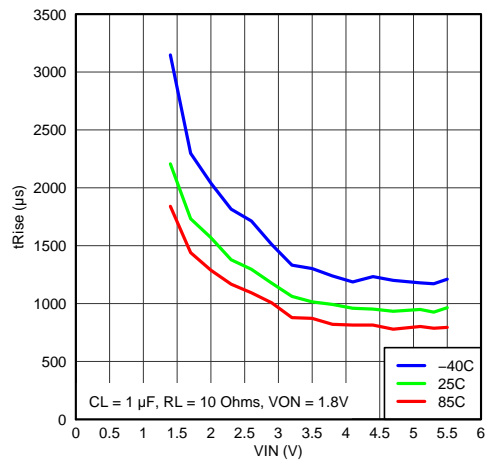


Figure 27. Rise Time vs Input Voltage

8.13 Typical AC Characteristics, TPS22913B

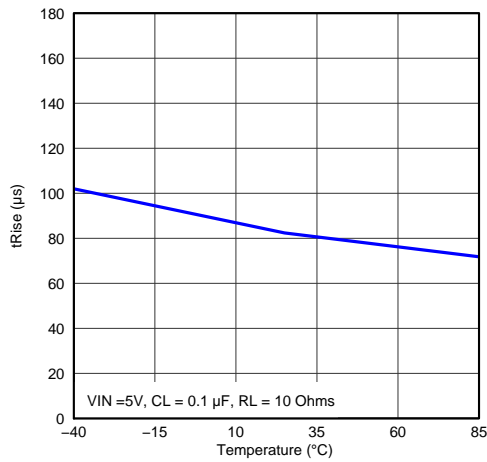


Figure 28. Rise Time vs Temperature

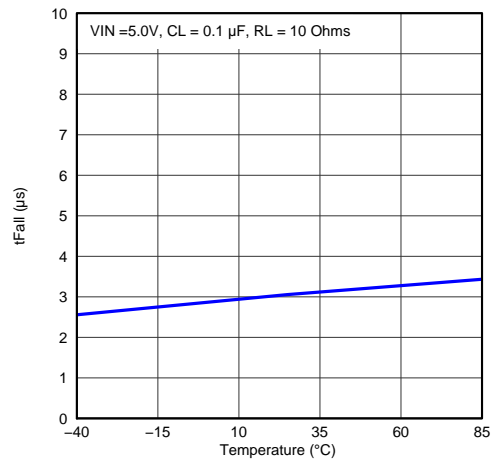


Figure 29. Fall Time vs Temperature

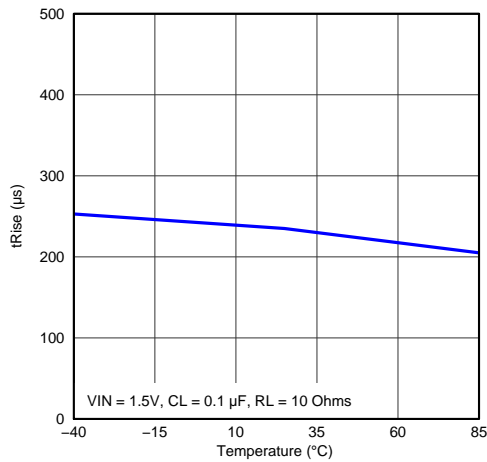


Figure 30. Rise Time vs Temperature

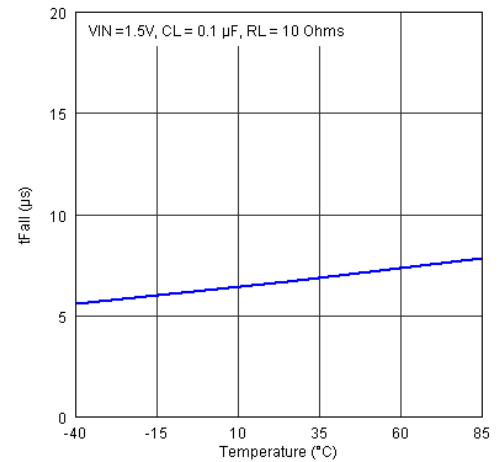


Figure 31. Fall Time vs Temperature

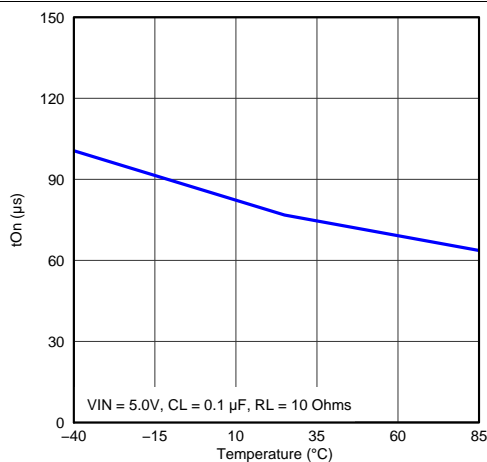


Figure 32. Turn-on Time vs Temperature

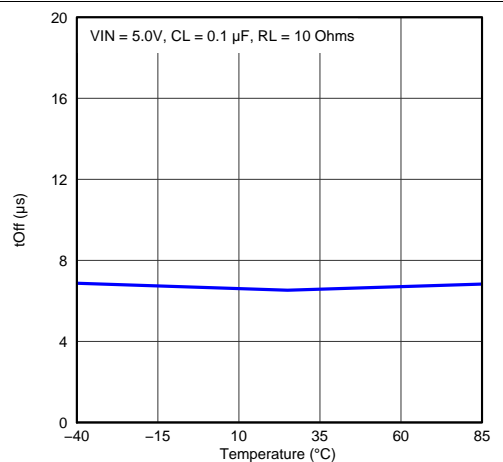


Figure 33. Turn-off Time vs Temperature

Typical AC Characteristics, TPS22913B (continued)

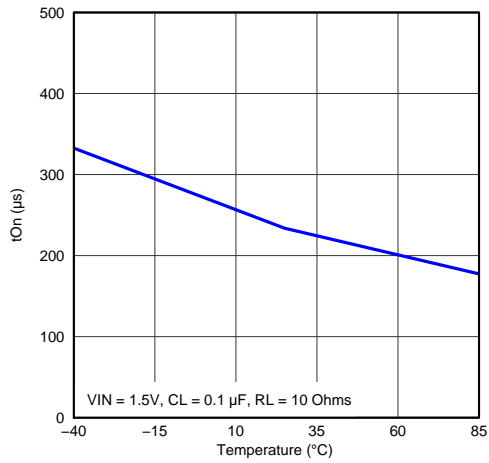


Figure 34. Turn-on Time vs Temperature

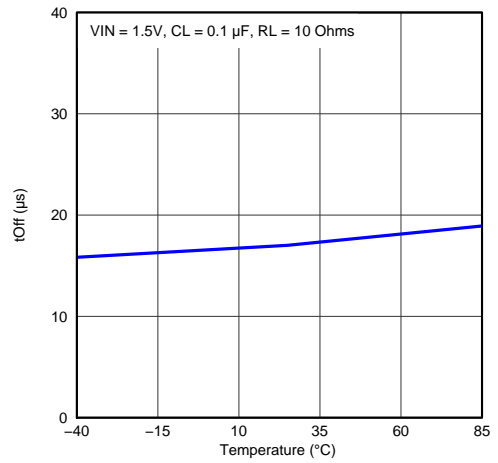


Figure 35. Turn-off Time vs Temperature

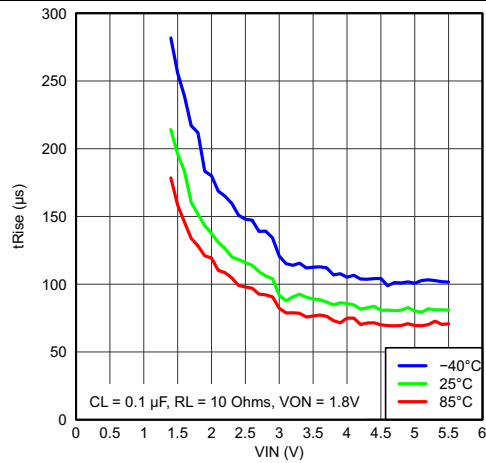


Figure 36. Rise Time vs Input Voltage

8.14 Typical AC Characteristics, TPS22913C

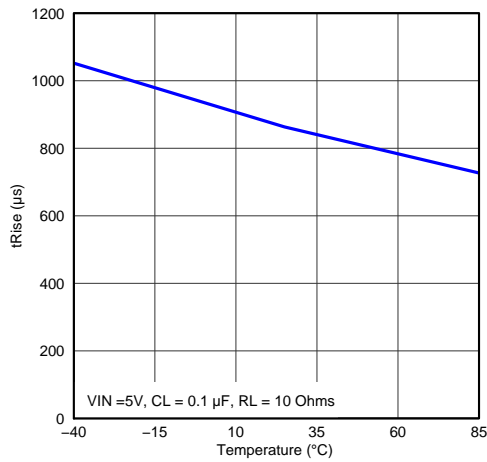


Figure 37. Rise Time vs Temperature

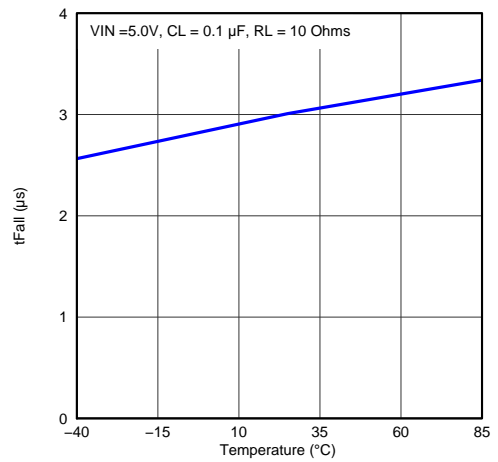


Figure 38. Fall Time vs Temperature

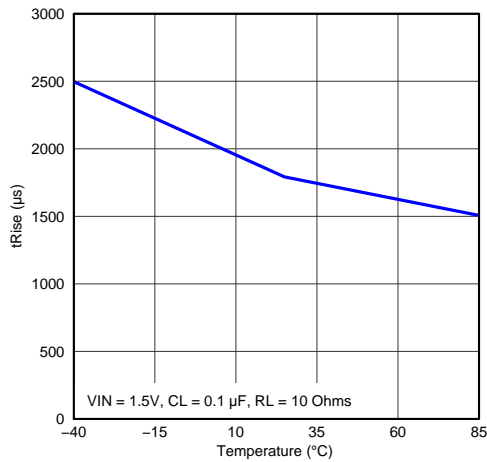


Figure 39. Rise Time vs Temperature

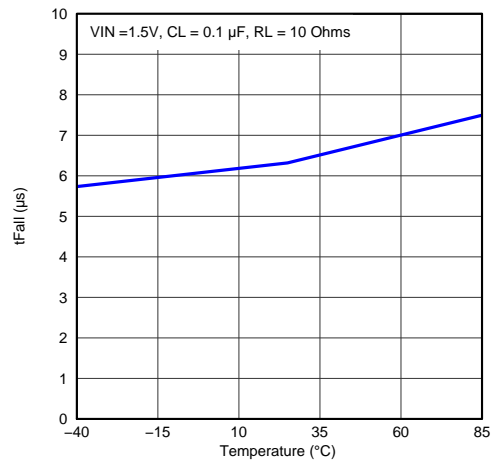


Figure 40. Fall Time vs Temperature

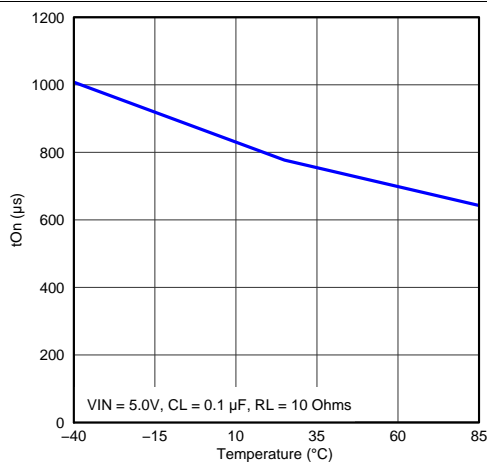


Figure 41. Turn-on Time vs Temperature

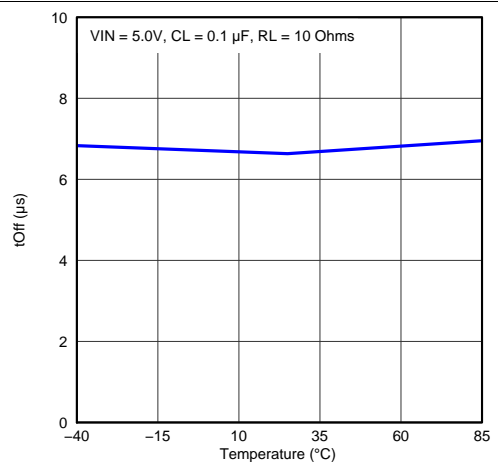


Figure 42. Turn-Off Time vs Temperature

Typical AC Characteristics, TPS22913C (continued)

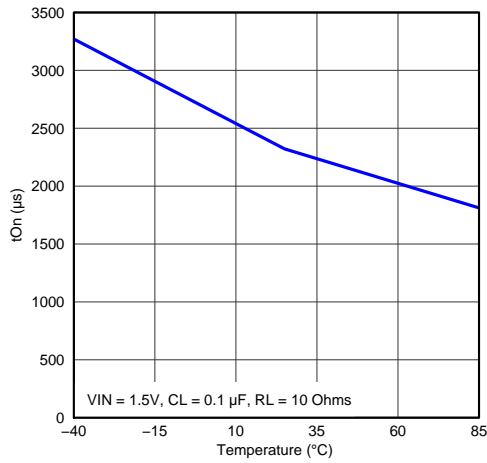


Figure 43. Turn-On Time vs Temperature

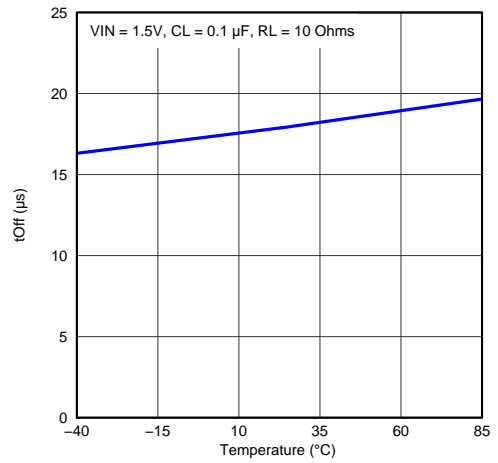


Figure 44. Turn-Off Time vs Temperature

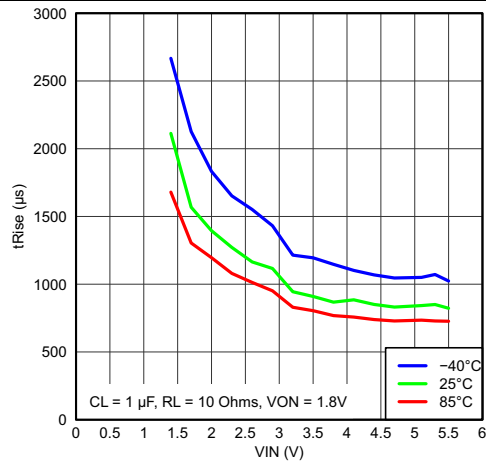


Figure 45. Rise Time vs Input Voltage

9 Parameter Measurement Information

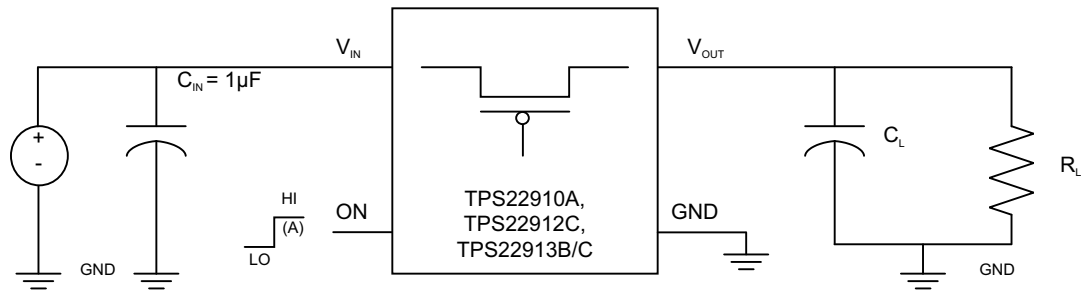
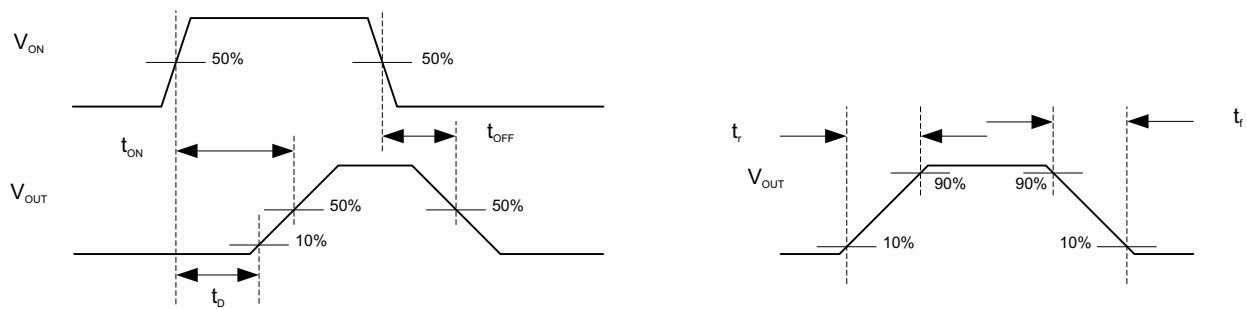


Figure 46. Timing Test Circuit



- A. Rise and fall times of the control signal is 100 ns.

Figure 47. Timing Waveforms

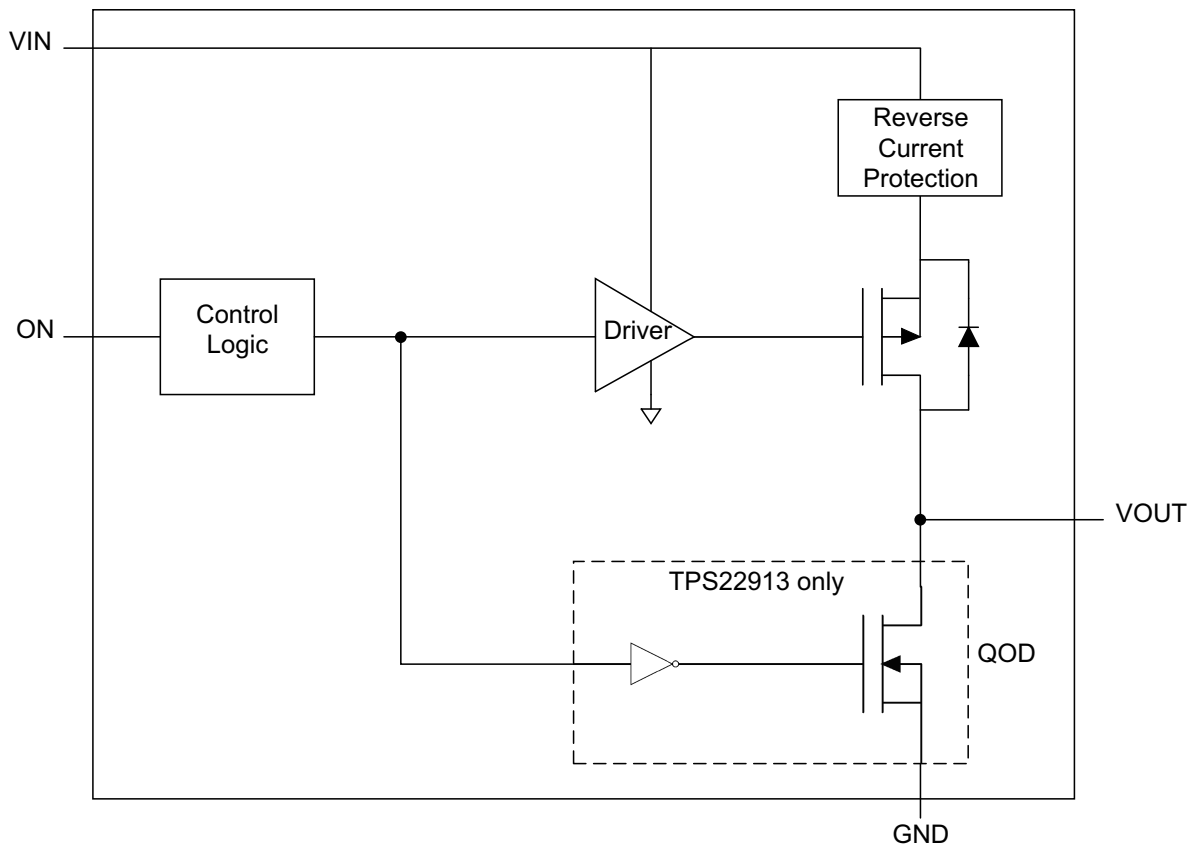
10 Detailed Description

10.1 Overview

This family of devices are single channel, 2-A load switches in ultra-small, space saving 4-pin WCSP package. These devices implement a low resistance P-channel MOSFET with a controlled rise time for applications that need to limit the inrush current.

These devices are designed to have very low leakage current during off state. This prevents downstream circuits from pulling high standby current from the supply. Integrated control logic, driver, power supply, and output discharge FET eliminates the need for additional external components, which reduces solution size and BOM count.

10.2 Functional Block Diagram



10.3 Feature Description

10.3.1 On/Off Control

The ON pin controls the state of the switch. The ON pin is compatible with standard GPIO logic threshold. It can be used with any microcontroller with 1.2-V, 1.8-V, 2.5-V, 3.3-V, or 5.5-V GPIO.

10.3.2 Under-Voltage Lockout

Under-voltage lockout protection turns off the switch if the input voltage drops below the under-voltage lockout threshold (UVLO). With the ON pin active, the input voltage rising above the under-voltage lockout threshold will cause a controlled turn-on of the switch to limit current over-shoot.

Feature Description (continued)

10.3.3 Full-Time Reverse Current Protection

In a scenario where V_{OUT} is greater than V_{IN} , there is potential for reverse current to flow through the pass FET or the body diode. The devices monitor V_{IN} and V_{OUT} voltage levels. When the reverse current voltage threshold (V_{RCP}) is exceeded, the switch is disabled (within 10 μ s typ). Additionally, the body diode is disengaged so as to prevent any reverse current flow to V_{IN} . The pass FET, and the output voltage (V_{OUT}), will resume normal operation when the reverse current scenario is no longer present. The peak instantaneous reverse current is the current it takes to trip the reverse current protection. After the reverse current protection has tripped due to the peak instantaneous reverse current, the DC (off-state) leakage current from V_{OUT} and V_{IN} is referred to as $I_{RCP(Leak)}$ (see Figure 48).

Use the following formula to calculate the amount of peak instantaneous reverse current for a particular application:

$$I_{RC} = \frac{V_{RCP}}{r_{ON(VIN)}}$$

Where,

I_{RC} is the amount of reverse current,

$r_{ON(VIN)}$ is the on-resistance at the V_{IN} of the reverse current condition.

V_{RCP} is the reverse voltage threshold.

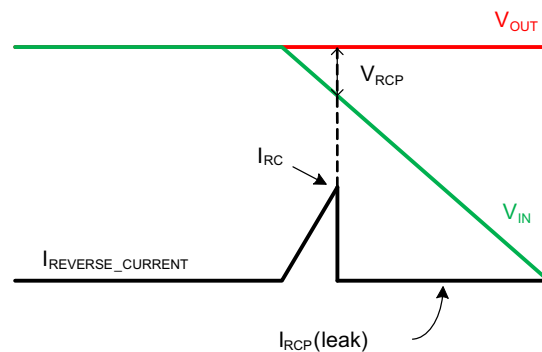


Figure 48. Reverse Current

10.4 Device Functional Modes

Table 2 describes what the V_{OUT} pin will be connected to for a particular device as determined by the V_{IN} pin

Table 2. VOUT Function Table

ON	TPS22910A	TPS22912C	TPS22913B/C
L	V_{IN}	Open	GND
H	Open	V_{IN}	V_{IN}

11 Application and Implementation

11.1 Application Information

This section will highlight some of the design considerations when implementing this device in various applications. A PSPICE model for this device is also available in the product page of this device on www.ti.com for further aid.

11.1.1 VIN to VOUT Voltage Drop

The VIN to VOUT voltage drop in the device is determined by the R_{ON} of the device and the load current. The R_{ON} of the device depends upon the VIN condition of the device. Refer to the R_{ON} specification of the device in the Electrical Characteristics table of this datasheet. Once the R_{ON} of the device is determined based upon the VIN conditions, use Equation 1 to calculate the VIN to VOUT voltage drop:

$$\Delta V = I_{LOAD} \times R_{ON} \quad (1)$$

Where,

ΔV = Voltage drop from VIN to VOUT

I_{LOAD} = Load current

R_{ON} = On-resistance of the device for a specific V_{IN}

An appropriate I_{LOAD} must be chosen such that the I_{MAX} specification of the device is not violated.

11.1.2 On/Off Control

The ON pin controls the state of the switch. The ON pin has a low threshold, making it capable of interfacing with low-voltage signals. The ON pin is compatible with standard GPIO logic thresholds. It can be used with any microcontroller with 1.2 V or higher GPIO voltage. This pin cannot be left floating and must be driven either high or low for proper functionality.

11.1.3 Input Capacitor (Optional)

To limit the voltage drop on the input supply caused by transient inrush currents when the switch turns on into a discharged load capacitor or short-circuit, a capacitor needs to be placed between V_{IN} and GND. A 1- μ F ceramic capacitor, C_{IN} , placed close to the pins, is usually sufficient. Higher values of C_{IN} can be used to further reduce the voltage drop during high current applications. When switching heavy loads, it is recommended to have an input capacitor about 10 times higher than the output capacitor to avoid excessive voltage drop.

11.1.4 Output Capacitor (Optional)

Due to the integrated body diode in the PMOS switch, a C_{IN} greater than C_L is highly recommended. A C_L greater than C_{IN} can cause V_{OUT} to exceed V_{IN} when the system supply is removed. This could result in current flow through the body diode from V_{OUT} to V_{IN} . A C_{IN} to C_L ratio of 10 to 1 is recommended for minimizing VIN dip caused by inrush currents during startup, however a 10 to 1 ratio for capacitance is not required for proper functionality of the device. A ratio smaller than 10 to 1 (such as 1 to 1) could cause slightly more V_{IN} dip upon turn-on due to inrush currents. This can be mitigated by using a device with a longer rise time.

11.2 Typical Application

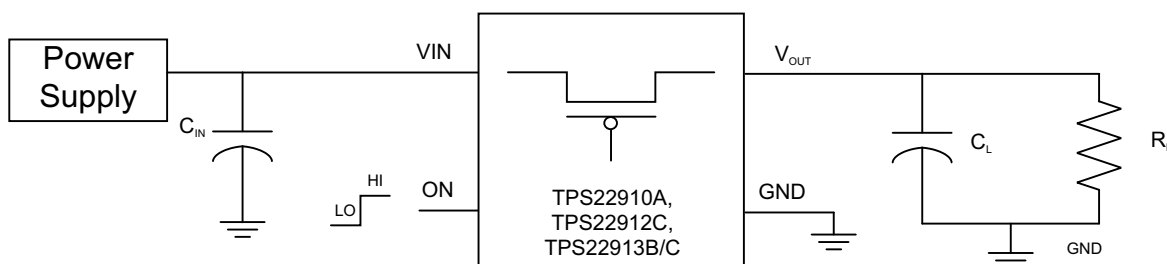


Figure 49. Typical Application

Typical Application (continued)

11.2.1 Design Requirements

Design Parameter	Example Value
VIN	1.5 V to 5 V
CL	0.1 μF to 1 μF
Maximum Acceptable Inrush Current	1 A

11.2.2 Detailed Design Procedure

11.2.2.1 Inrush Current

When the switch is enabled, the output capacitors must be charged up from 0-V to VIN voltage. This charge arrives in the form of inrush current. Inrush current can be calculated using the following equation:

$$\text{Inrush Current} = C \times \frac{dv}{dt} \quad (2)$$

Where,

C = Output capacitance

$\frac{dv}{dt}$ = Output slew rate

The TPS22910A, TPS22912C, and TPS22913B/C offer several different rise time options to control the inrush current during turn-on. The appropriate device can be selected based upon the maximum acceptable slew rate which can be calculated using the design requirements and the inrush current equation. An output capacitance of 1.0 μF will be used since the inrush follows the following equations:

$$1.0 \text{ A} = 1.0 \mu\text{F} \times \frac{dv}{dt} \quad (3)$$

$$\frac{dv}{dt} = 1 \text{ V}/\mu\text{s} \quad (4)$$

To ensure an inrush current of less than 1 A, a device with a slew rate less than 1 V/μs must be used

The TPS22910A has a typical rise time of 1 μs at 3.3 V. This results in a slew rate of 3.3 V/μs which is above the 1 V/μs requirement meaning the TPS22910 could not be used to meet the design requirements.

The TPS22913B has a typical rise time of 66 μs at 3.3 V. This results in a slew rate of 50 mV/μs which is below the 1 V/μs requirement; therefore, the TPS22913B could be used to meet the design requirements. The TPS22912C or TPS22913C have lower slew rates than the TPS22913B, so they could also be used, but the output would rise more slowly.

11.2.3 Application Curves

11.2.3.1 Typical Application Characteristics for TPS22910A

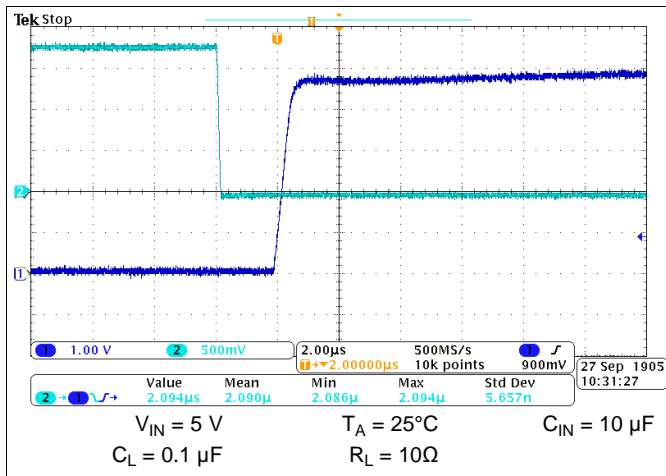


Figure 50. Turn-on Response

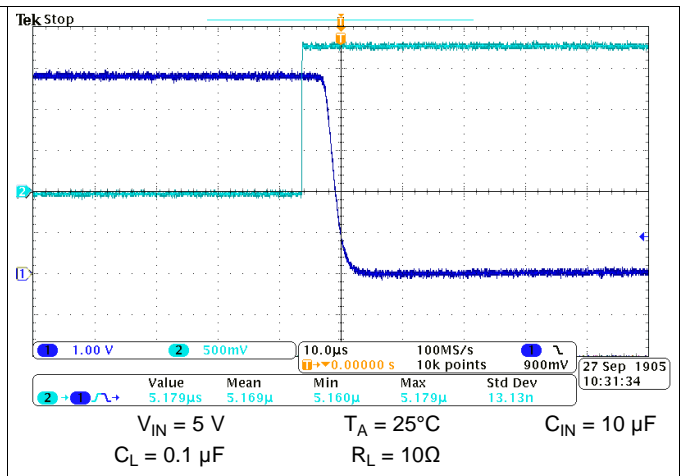


Figure 51. Turn-off Response

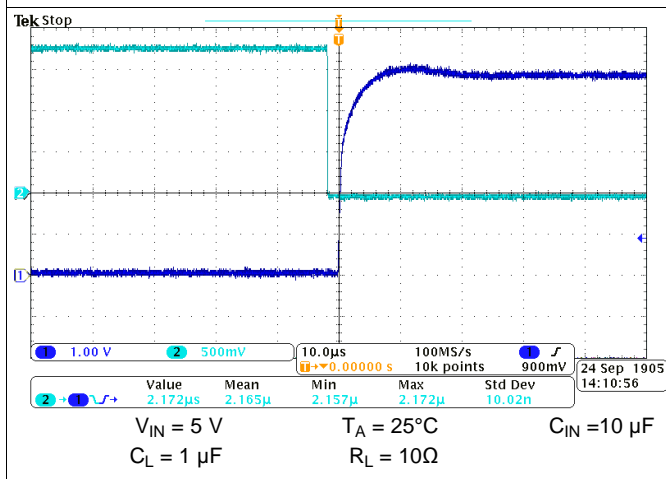


Figure 52. Turn-on Response Time

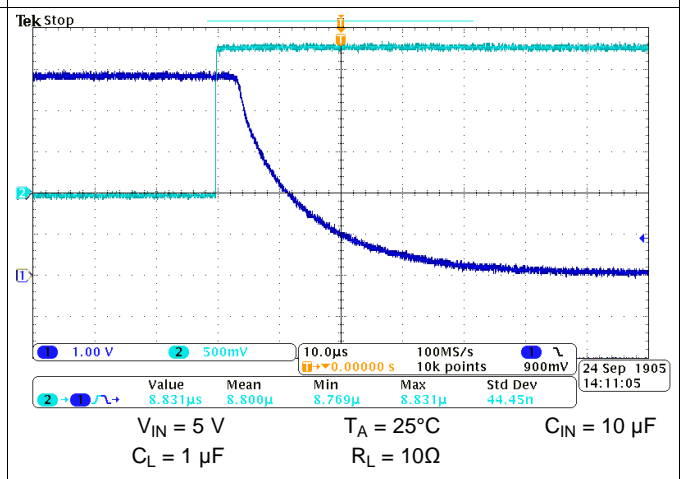


Figure 53. Turn-off Response Time

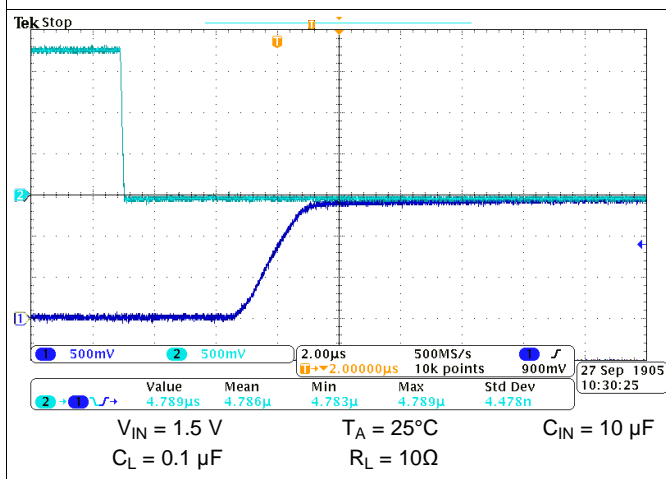


Figure 54. Turn-on Response Time

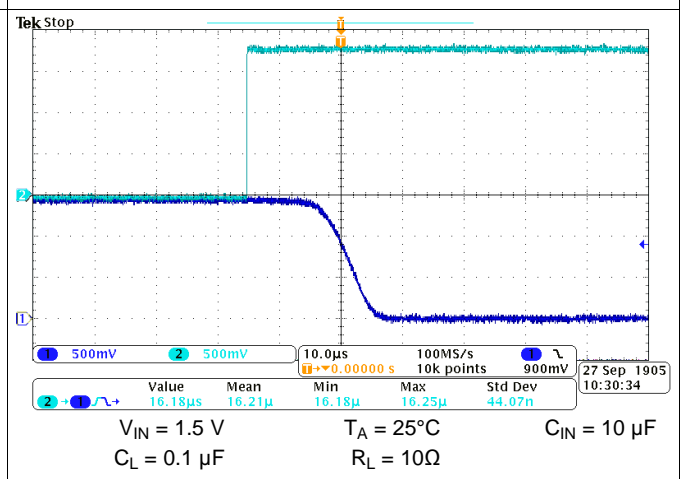
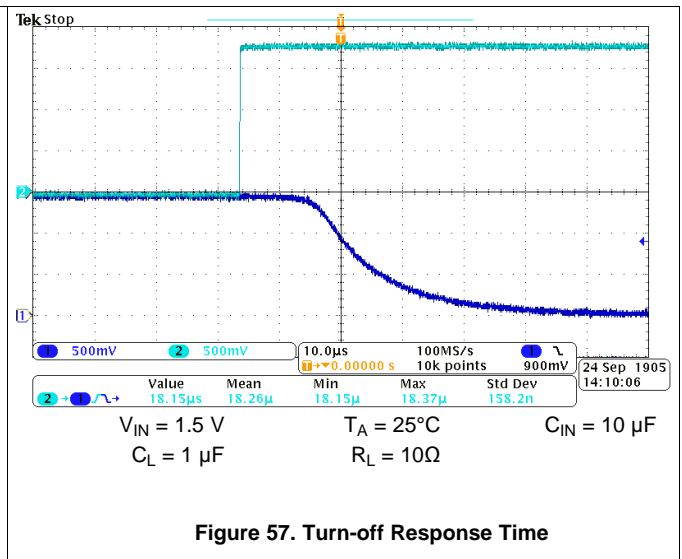
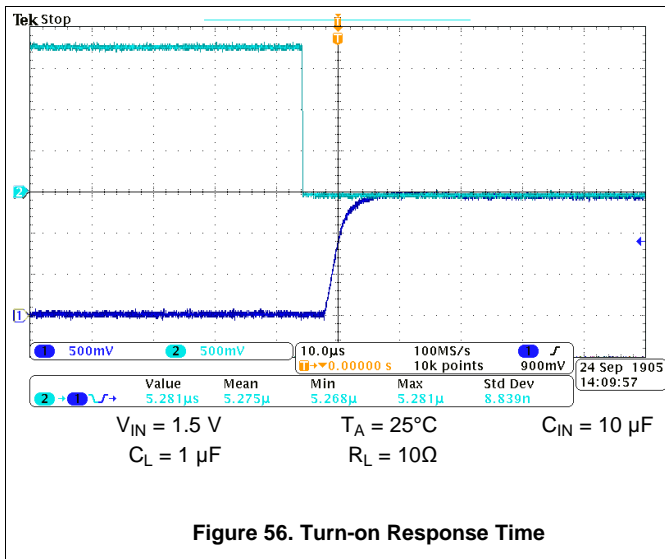


Figure 55. Turn-off Response Time



11.2.3.2 Typical Application Characteristics for TPS22912C

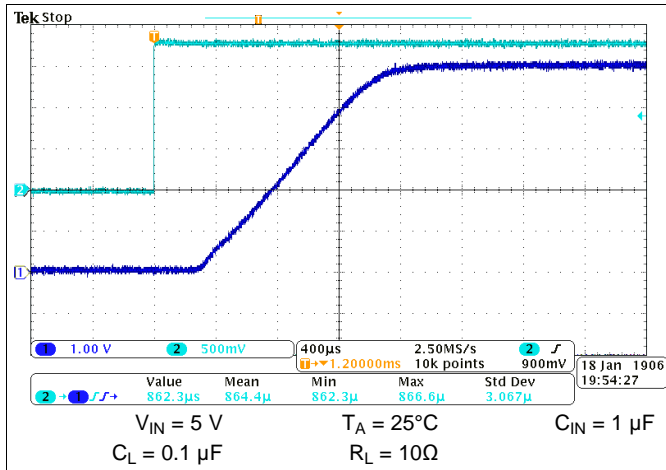


Figure 58. Turn-on Response

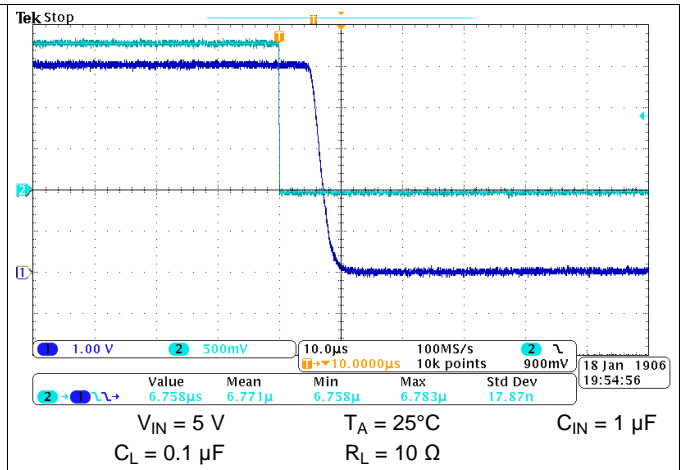


Figure 59. Turn-off Response

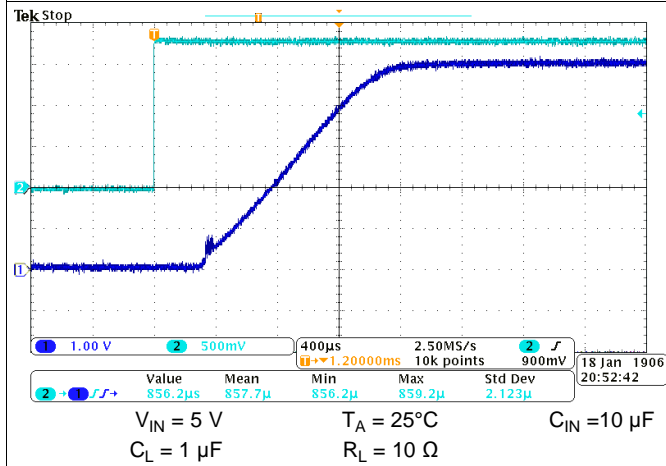


Figure 60. Turn-on Response Time

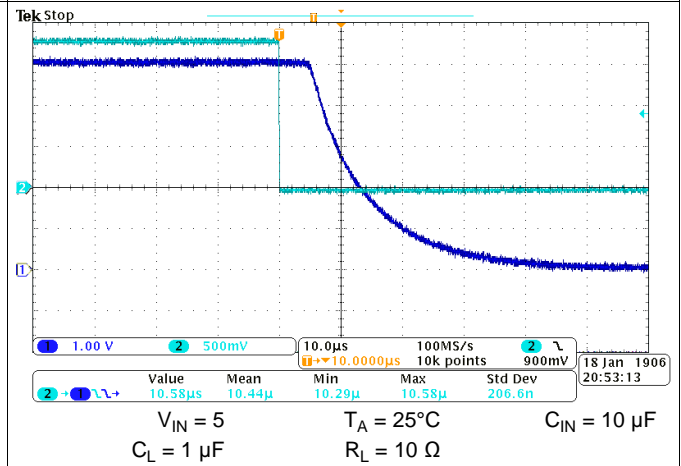


Figure 61. Turn-off Response Time

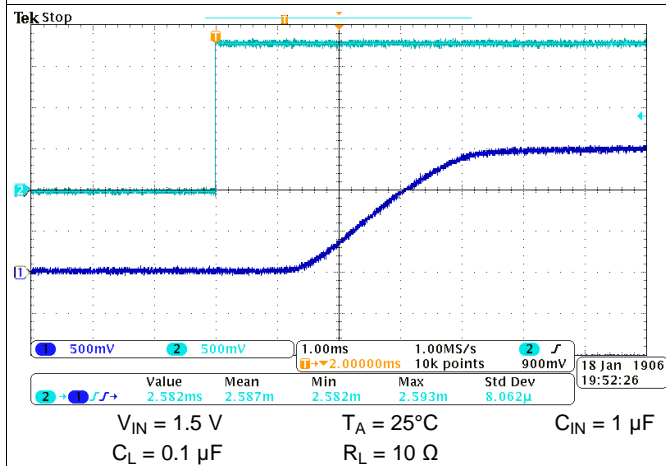


Figure 62. Turn-on Response Time

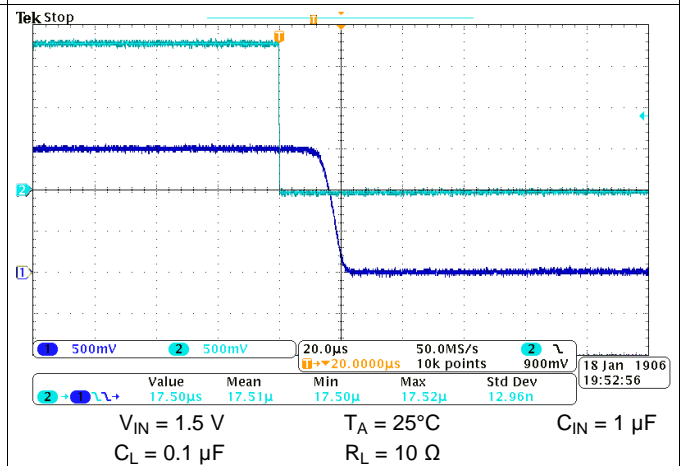
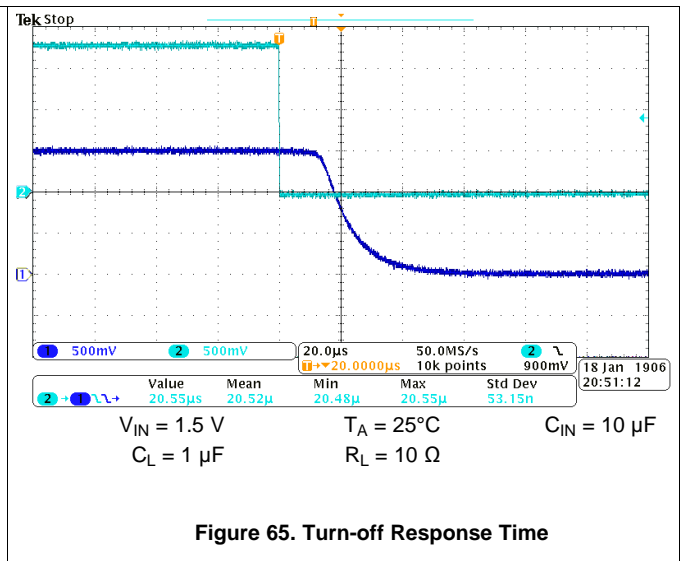
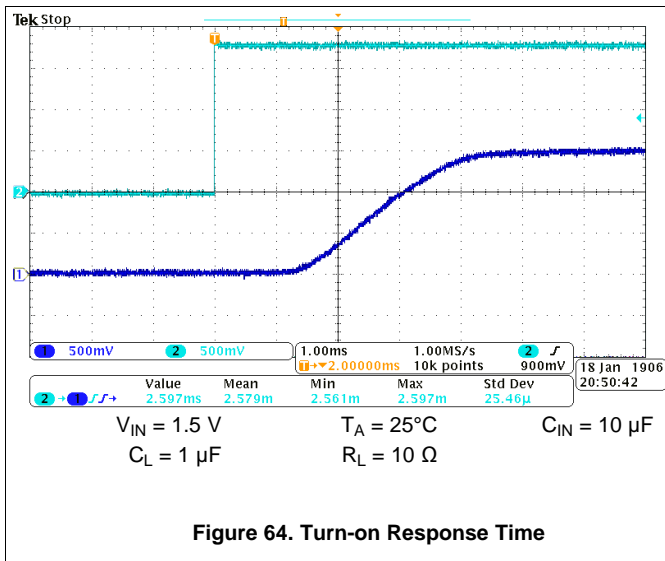


Figure 63. Turn-off Response Time



11.2.3.3 Typical Application Characteristics For TPS22913B

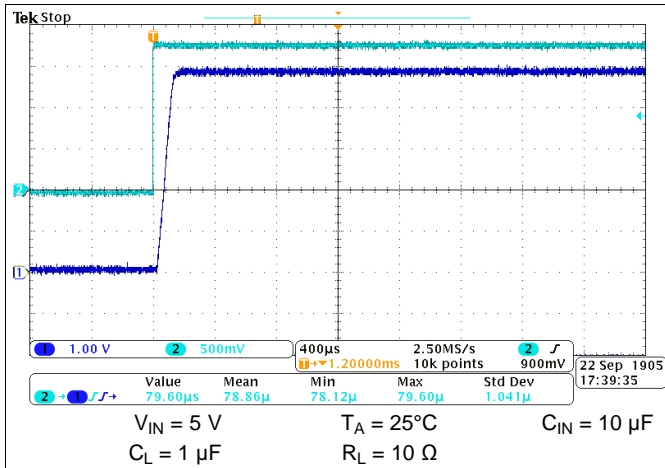


Figure 66. Turn-on Response

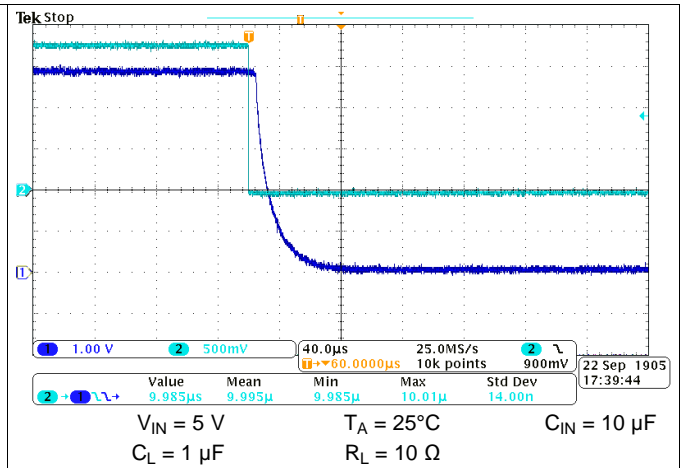


Figure 67. Turn-off Response

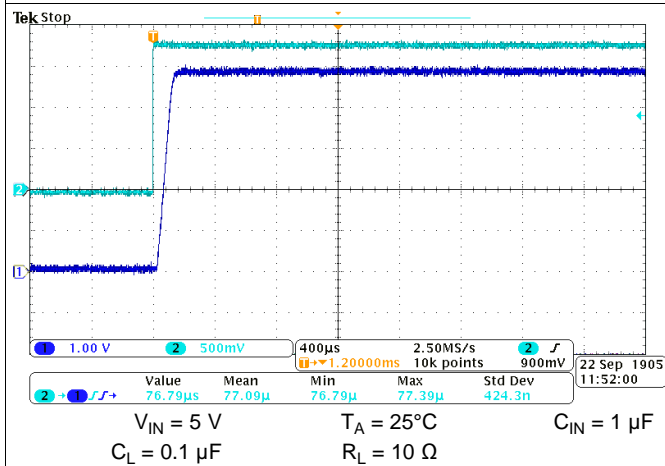


Figure 68. Turn-on Response Time

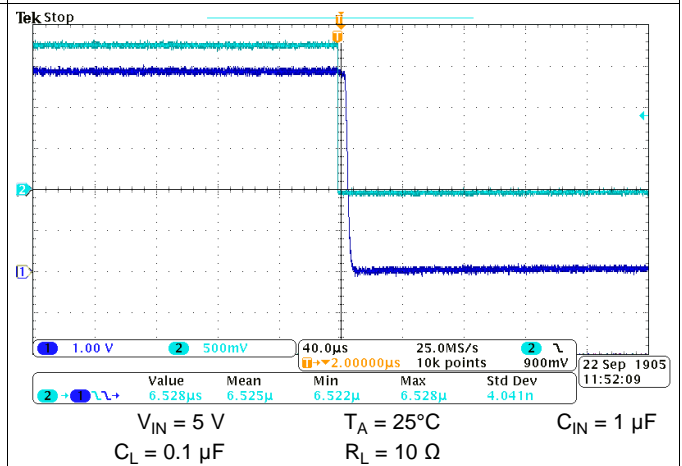


Figure 69. Turn-off Response Time

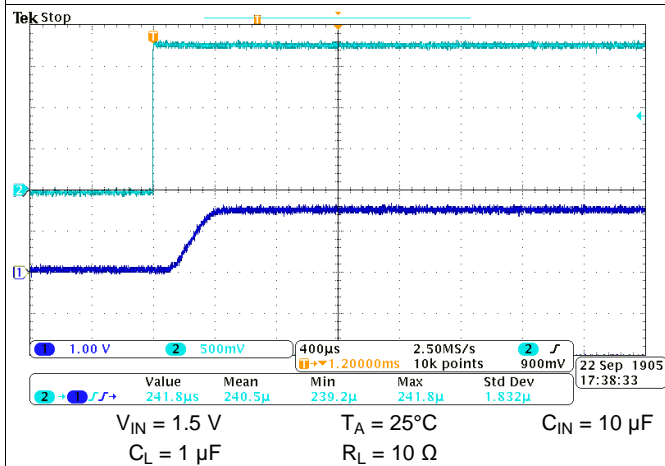


Figure 70. Turn-on Response Time

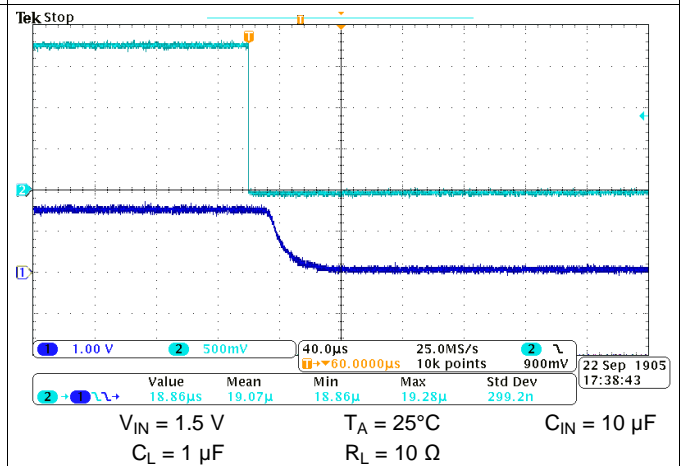
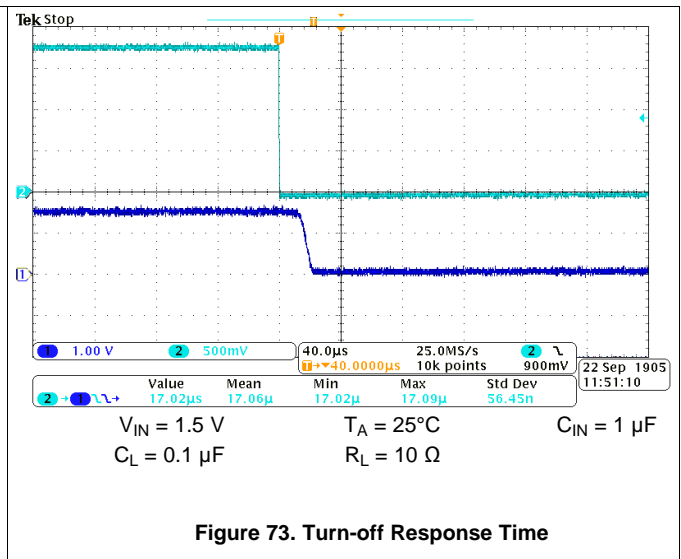
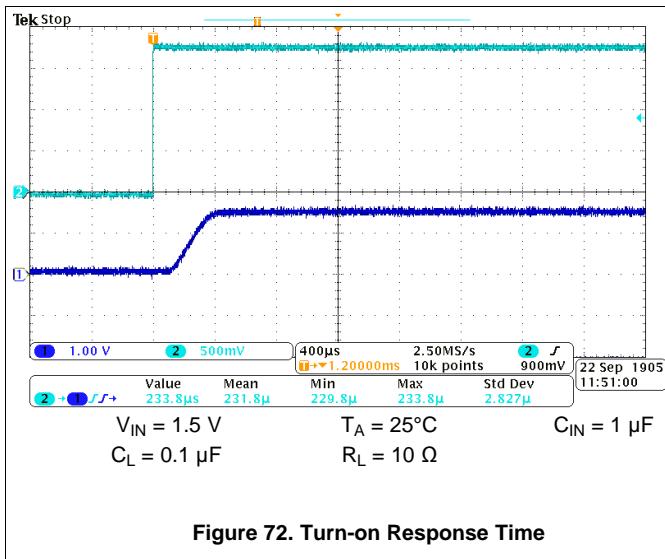


Figure 71. Turn-off Response Time



11.2.3.4 Typical Application Characteristics for TPS22913C

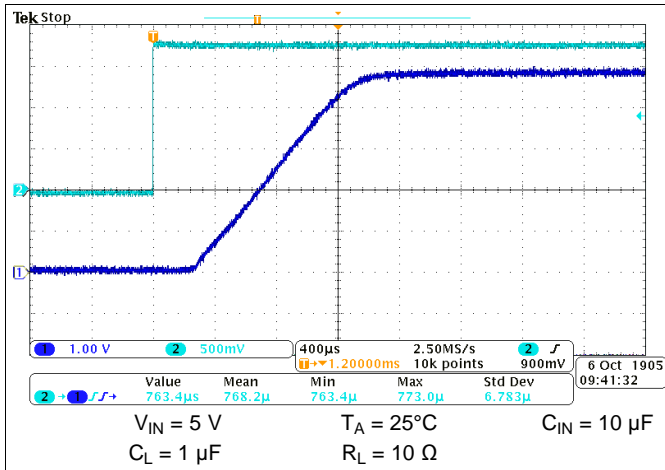


Figure 74. Turn-On Response Time

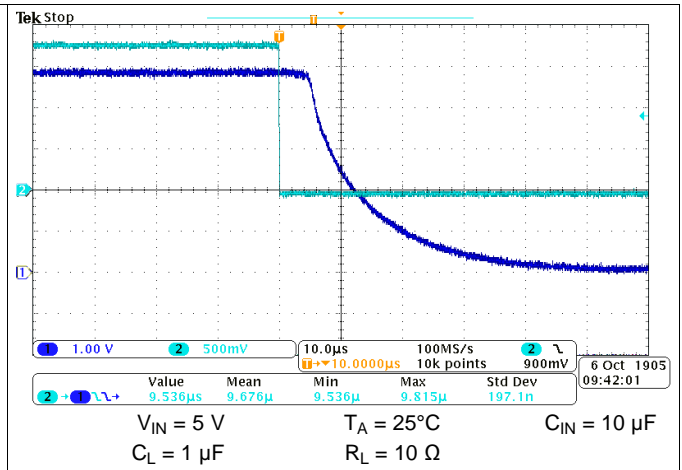


Figure 75. Turn-Off Response Time

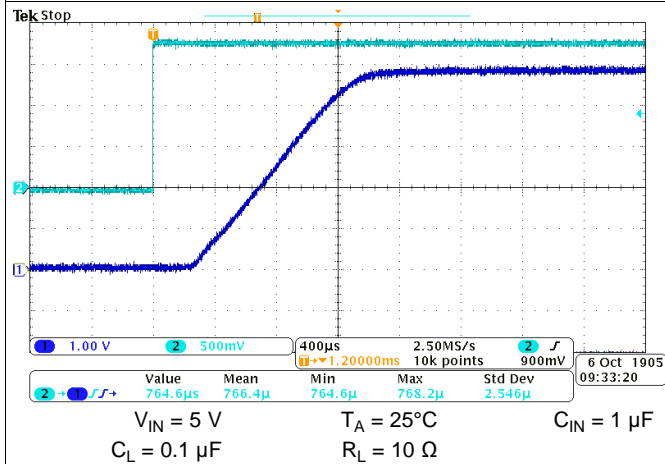


Figure 76. Turn-On Response Time

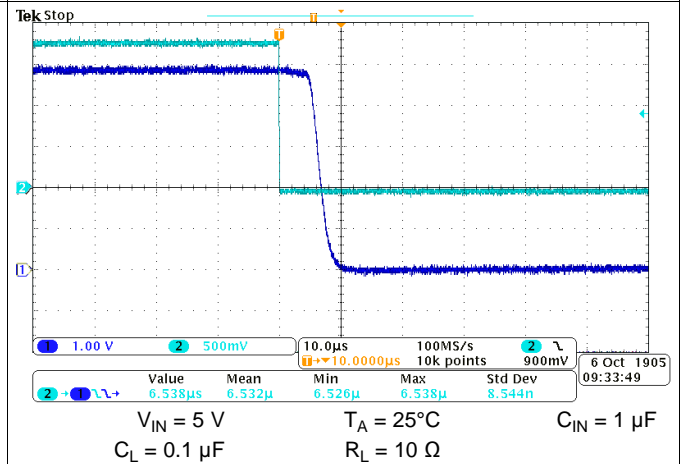


Figure 77. Turn-Off Response Time

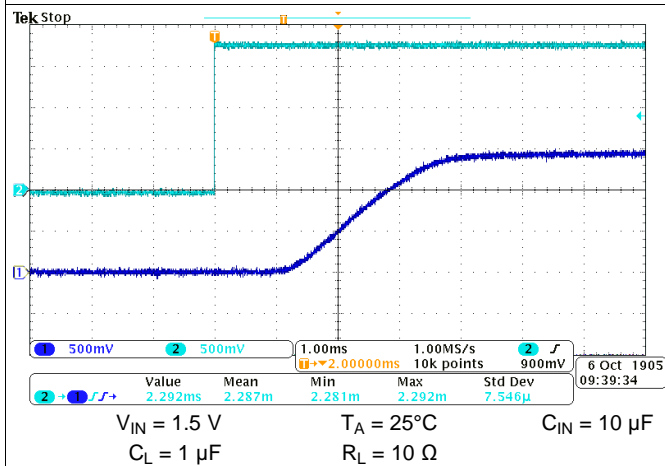


Figure 78. Turn-Off Response Time

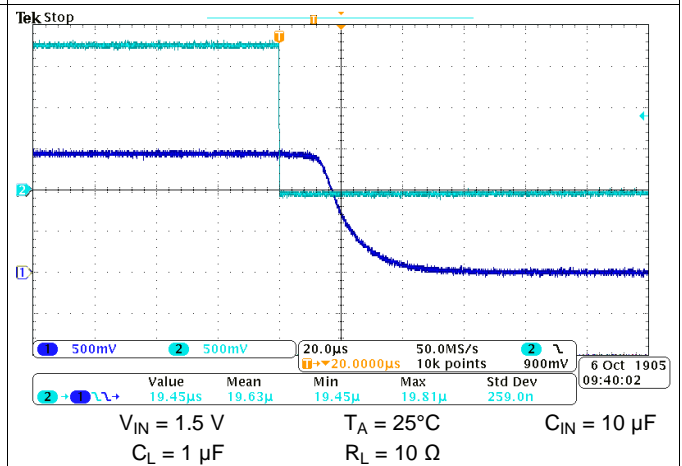
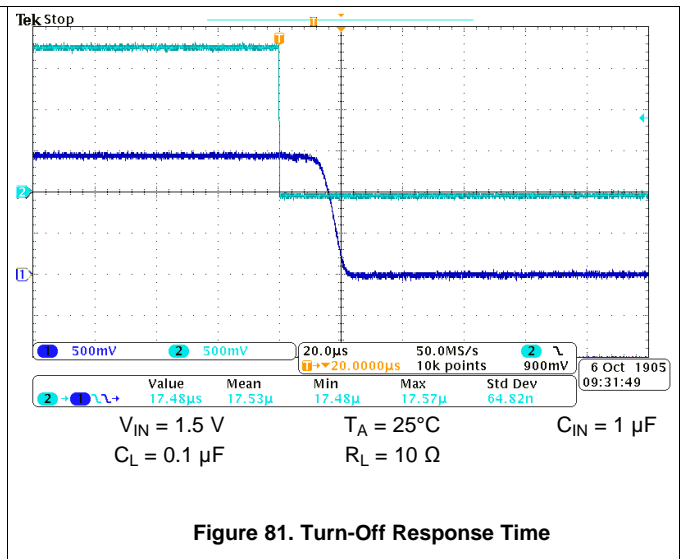
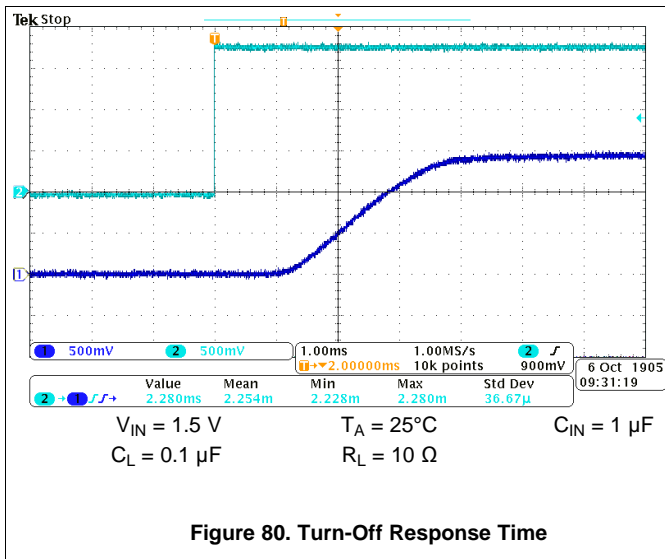


Figure 79. Turn-Off Response Time



12 Power Supply Recommendations

The device is designed to operate with a V_{IN} range of 1.4 V to 5.5 V.

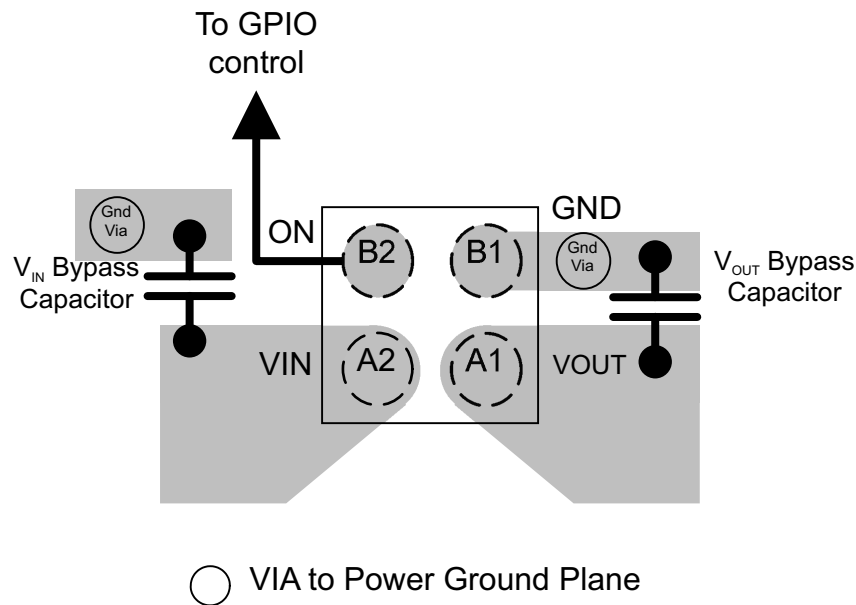
13 Layout

13.1 Layout Guidelines

For best performance, all traces should be as short as possible. To be most effective, the input and output capacitors should be placed close to the device to minimize the effects that parasitic trace inductances may have on normal operation. Using wide traces for V_{IN} , V_{OUT} , and GND helps minimize the parasitic electrical effects along with minimizing the case to ambient thermal impedance.

13.2 Layout Example

The figure below shows an example of a layout. Notice the thermal vias located under the exposed thermal pad of the device. This allows for thermal diffusion away from the device.



13.3 Thermal Considerations

The maximum IC junction temperature should be restricted to 125°C under normal operating conditions. To calculate the maximum allowable dissipation, $P_{D(max)}$ for a given output current and ambient temperature, use the following equation as a guideline:

$$P_{D(max)} = \frac{T_{J(MAX)} - T_A}{\theta_{JA}} \quad (5)$$

where

- $P_{D(max)}$ = maximum allowable power dissipation
- $T_{J(max)}$ = maximum allowable junction temperature
- T_A = ambient temperature of the device
- θ_{JA} = junction to air thermal impedance. See the [Thermal Information](#) section. This parameter is highly dependent upon board layout.

14 Device and Documentation Support

14.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 3. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
TPS22910A	Click here	Click here	Click here	Click here	Click here
TPS22912C	Click here	Click here	Click here	Click here	Click here
TPS22913B	Click here	Click here	Click here	Click here	Click here
TPS22913C	Click here	Click here	Click here	Click here	Click here

14.2 Trademarks

Ultrabook is a trademark of Intel.

14.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

14.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms and definitions.

15 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS22910AYZVR	ACTIVE	DSBGA	YZV	4	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	75	Samples
TPS22910AYZVT	ACTIVE	DSBGA	YZV	4	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	75	Samples
TPS22912CYZVR	ACTIVE	DSBGA	YZV	4	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	78	Samples
TPS22912CYZVT	ACTIVE	DSBGA	YZV	4	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	78	Samples
TPS22913BYZVR	ACTIVE	DSBGA	YZV	4	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	64	Samples
TPS22913BYZVT	ACTIVE	DSBGA	YZV	4	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	64	Samples
TPS22913CYZVR	ACTIVE	DSBGA	YZV	4	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	76	Samples
TPS22913CYZVT	ACTIVE	DSBGA	YZV	4	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	76	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS22910AYZVR	DSBGA	YZV	4	3000	178.0	9.2	1.0	1.0	0.63	4.0	8.0	Q1
TPS22910AYZVT	DSBGA	YZV	4	250	178.0	9.2	1.0	1.0	0.63	4.0	8.0	Q1
TPS22912CYZVR	DSBGA	YZV	4	3000	178.0	9.2	1.0	1.0	0.63	4.0	8.0	Q1
TPS22912CYZVT	DSBGA	YZV	4	250	178.0	9.2	1.0	1.0	0.63	4.0	8.0	Q1
TPS22913BYZVR	DSBGA	YZV	4	3000	178.0	9.2	1.0	1.0	0.63	4.0	8.0	Q1
TPS22913BYZVT	DSBGA	YZV	4	250	178.0	9.2	1.0	1.0	0.63	4.0	8.0	Q1
TPS22913CYZVR	DSBGA	YZV	4	3000	178.0	9.2	1.0	1.0	0.63	4.0	8.0	Q1
TPS22913CYZVT	DSBGA	YZV	4	250	178.0	9.2	1.0	1.0	0.63	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS22910AYZVR	DSBGA	YZV	4	3000	220.0	220.0	35.0
TPS22910AYZVT	DSBGA	YZV	4	250	220.0	220.0	35.0
TPS22912CZVR	DSBGA	YZV	4	3000	220.0	220.0	35.0
TPS22912CZVT	DSBGA	YZV	4	250	220.0	220.0	35.0
TPS22913BZVR	DSBGA	YZV	4	3000	220.0	220.0	35.0
TPS22913BZVT	DSBGA	YZV	4	250	220.0	220.0	35.0
TPS22913CZVR	DSBGA	YZV	4	3000	220.0	220.0	35.0
TPS22913CZVT	DSBGA	YZV	4	250	220.0	220.0	35.0

YZV (S-XBGA-N4)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.

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